

# 具有 70V 总线故障保护功能和灵活数据速率的 ISO1042-Q1 汽车隔离式 CAN 收发器

## 1 特性

- AEC Q100 标准：符合汽车应用要求
- 1 级：-40°C 至 +125°C 环境温度
- 提供功能安全
  - 可提供用于功能安全系统设计的文档
- 符合 ISO 11898-2:2016 物理层标准
- 支持经典的最高 1Mbps CAN 和最高 5Mbps FD (灵活数据速率)
- 低环路延迟：152ns
- 保护特性
  - 直流总线故障保护电压： $\pm 70V$
  - 总线引脚的 HBM ESD 容差： $\pm 16kV$
  - 驱动器显性超时 (TXD DTO)
  - $V_{CC1}$  和  $V_{CC2}$  欠压保护
- 共模电压范围： $\pm 30V$
- 未上电时的理想无源、高阻抗总线终端
- 高 CMTI：100kV/ $\mu s$
- $V_{CC1}$  电压范围：1.71V 至 5.5V
  - 支持连接到 CAN 控制器的 1.8V、2.5V、3.3V 和 5.0V 逻辑接口
- $V_{CC2}$  电压范围：4.5V 至 5.5V
- 优异的电磁兼容性 (EMC)
  - 系统级 ESD、EFT 和浪涌抗扰性
  - 低辐射
- 16-SOIC 和 8-SOIC 封装选项
- 提供工业版本：[ISO1042](#)
- 安全相关认证：
  - 符合 DIN VDE V 0884-11:2017-01 标准的 7071V<sub>PK</sub>  $V_{IOTM}$  和 1500V<sub>PK</sub>  $V_{IORM}$  (增强型和基本型选项)
  - UL 1577 标准下，长达 1 分钟的 5000V<sub>RMS</sub> 隔离
  - CQC、TUV 和 CSA 认证

5Mbps 数据速率，与经典 CAN 相比可实现更为快速的载荷传输。该器件采用二氧化硅 (SiO<sub>2</sub>) 绝缘隔栅，可承受 5000V<sub>RMS</sub> 的电压和 1060V<sub>RMS</sub> 的工作电压。电磁兼容性得到了显著增强，可实现系统级 ESD、EFT 和浪涌并符合辐射标准。与隔离式电源一起使用，此器件可抵御高电压冲击，并防止总线的噪声电流进入本地接地。ISO1042-Q1 器件提供基础型和增强型隔离 (请参阅 [增强型和基础型隔离选项](#))。ISO1042-Q1 器件支持 -40°C 至 +125°C 的宽环境温度范围，该器件采用 SOIC-16 (DW) 封装和较小的 SOIC-8 (DWV) 封装。

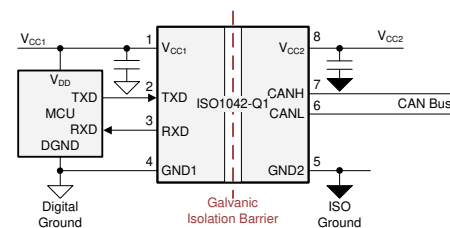
### 器件信息

| 器件型号 <sup>(1)</sup> | 封装        | 封装尺寸 (标称值)       |
|---------------------|-----------|------------------|
| ISO1042-Q1          | SOIC (8)  | 5.85mm × 7.50mm  |
|                     | SOIC (16) | 10.30mm × 7.50mm |

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。

### 增强型和基础型隔离选项

| 特性     | ISO1042x-Q1                                   | ISO1042Bx-Q1                                  |
|--------|-----------------------------------------------|-----------------------------------------------|
| 保护级别   | 增强型                                           | 基本型                                           |
| 浪涌测试电压 | 10000V <sub>PK</sub>                          | 6000V <sub>PK</sub>                           |
| 隔离额定值  | 5000V <sub>RMS</sub>                          | 5000V <sub>RMS</sub>                          |
| 工作电压   | 1060V <sub>RMS</sub> /<br>1500V <sub>PK</sub> | 1060V <sub>RMS</sub> /<br>1500V <sub>PK</sub> |



应用示意图

## 2 应用

- 起动机/发电机
- 电池管理系统 (BMS)
- 直流/直流转换器
- 车载充电器 (OBC) 和无线充电器
- 逆变器和电机控制

## 3 说明

ISO1042-Q1 器件是一款符合 ISO11898-2 (2016) 标准规格的电隔离控制器局域网 (CAN) 收发器。ISO1042-Q1 器件提供  $\pm 70V$  直流母线故障保护功能和  $\pm 30V$  共模电压范围。该器件在 CAN FD 模式下最高支持



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## 4 Revision History

注：以前版本的页码可能与当前版本的页码不同

| Changes from Revision A (January 2020) to Revision B (October 2020) | Page |
|---------------------------------------------------------------------|------|
| • 添加了“功能安全”要点.....                                                  | 1    |
| Changes from Revision * (October 2018) to Revision A (January 2020) | Page |
| • 更改了新的安全认证.....                                                    | 1    |

## 5 Pin Configuration and Functions

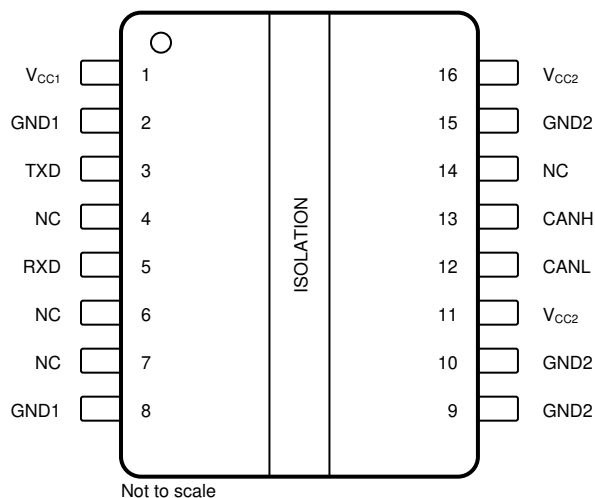


图 5-1. DW Package 16-Pin SOIC Top View

表 5-1. Pin Functions—16 Pins

| PIN |                  | I/O | DESCRIPTION                                                                      |
|-----|------------------|-----|----------------------------------------------------------------------------------|
| NO. | NAME             |     |                                                                                  |
| 1   | V <sub>CC1</sub> | —   | Digital-side supply voltage, Side 1                                              |
| 2   | GND1             | —   | Digital-side ground connection, Side 1                                           |
| 3   | TXD              | I   | CAN transmit data input (LOW for dominant and HIGH for recessive bus states)     |
| 4   | NC               | —   | Not connected                                                                    |
| 5   | RXD              | O   | CAN receive data output (LOW for dominant and HIGH for recessive bus states)     |
| 6   | NC               | —   | Not connected                                                                    |
| 7   | NC               | —   | Not connected                                                                    |
| 8   | GND1             | —   | Digital-side ground connection, Side 1                                           |
| 9   | GND2             | —   | Transceiver-side ground connection, Side 2                                       |
| 10  |                  |     |                                                                                  |
| 11  | V <sub>CC2</sub> | —   | Transceiver-side supply voltage, Side 2. Must be externally connected to pin 16. |
| 12  | CANL             | I/O | Low-level CAN bus line                                                           |
| 13  | CANH             | I/O | High-level CAN bus line                                                          |
| 14  | NC               | —   | Not connected                                                                    |
| 15  | GND2             | —   | Transceiver-side ground connection, Side 2                                       |
| 16  | V <sub>CC2</sub> | —   | Transceiver-side supply voltage, Side 2. Must be externally connected to pin 11. |

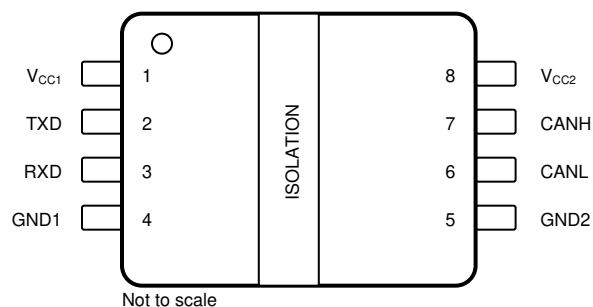


图 5-2. DWV Package 8-Pin SOIC Top View

表 5-2. Pin Functions—8 Pins

| PIN |                  | I/O | DESCRIPTION                                                                  |
|-----|------------------|-----|------------------------------------------------------------------------------|
| NO. | NAME             |     |                                                                              |
| 1   | V <sub>CC1</sub> | —   | Digital-side supply voltage, Side 1                                          |
| 2   | TXD              | I   | CAN transmit data input (LOW for dominant and HIGH for recessive bus states) |
| 3   | RXD              | O   | CAN receive data output (LOW for dominant and HIGH for recessive bus states) |
| 4   | GND1             | —   | Digital-side ground connection, Side 1                                       |
| 5   | GND2             | —   | Transceiver-side ground connection, Side 2                                   |
| 6   | CANL             | I/O | Low-level CAN bus line                                                       |
| 7   | CANH             | I/O | High-level CAN bus line                                                      |
| 8   | V <sub>CC2</sub> | —   | Transceiver-side supply voltage, Side 2                                      |

## 6 Specifications

### 6.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)<sup>(1) (2)</sup>

|                       |                                                    | MIN  | MAX                                  | UNIT |
|-----------------------|----------------------------------------------------|------|--------------------------------------|------|
| V <sub>CC1</sub>      | Supply voltage, side 1                             | -0.5 | 6                                    | V    |
| V <sub>CC2</sub>      | Supply voltage, side 2                             | -0.5 | 6                                    | V    |
| V <sub>IO</sub>       | Logic input and output voltage range (TXD and RXD) | -0.5 | V <sub>CC1</sub> +0.5 <sup>(3)</sup> | V    |
| I <sub>O</sub>        | Output current on RXD pin                          | -15  | 15                                   | mA   |
| V <sub>BUS</sub>      | Voltage on bus pins (CANH, CANL)                   | -70  | 70                                   | V    |
| V <sub>BUS_DIFF</sub> | Differential voltage on bus pins (CANH-CANL)       | -70  | 70                                   | V    |
| T <sub>J</sub>        | Junction temperature                               | -40  | 150                                  | °C   |
| T <sub>STG</sub>      | Storage temperature                                | -65  | 150                                  | °C   |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values except differential I/O bus voltages are with respect to the local ground terminal (GND1 or GND2) and are peak voltage values.
- (3) Maximum voltage must not exceed 6 V

### 6.2 ESD Ratings

|                    |                                                                                               |                                      | VALUE  | UNIT |
|--------------------|-----------------------------------------------------------------------------------------------|--------------------------------------|--------|------|
| V <sub>(ESD)</sub> | Electrostatic discharge<br>Human body model (HBM), per ANSI/<br>ESDA/JEDEC JS-001             | All pins <sup>(1)</sup>              | ±6000  | V    |
|                    |                                                                                               | CANH and CANL to GND2 <sup>(1)</sup> | ±16000 | V    |
|                    | Electrostatic discharge<br>Charged device model (CDM), per<br>JEDEC specification JESD22-C101 | All pins <sup>(2)</sup>              | ±1500  |      |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Transient Immunity

| PARAMETER          | TEST CONDITIONS                                                            | VALUE                                               | UNIT   |
|--------------------|----------------------------------------------------------------------------|-----------------------------------------------------|--------|
| V <sub>PULSE</sub> | ISO7637-2 Transients according to GIFT - ICT<br>CAN EMC test specification | Pulse 1; CAN bus terminals (CANH, CANL) to<br>GND2  | -100 V |
|                    |                                                                            | Pulse 2; CAN bus terminals (CANH, CANL) to<br>GND2  | 75 V   |
|                    |                                                                            | Pulse 3a; CAN bus terminals (CANH, CANL) to<br>GND2 | -150 V |
|                    |                                                                            | Pulse 3b; CAN bus terminals (CANH, CANL) to<br>GND2 | 100 V  |

### 6.4 Recommended Operating Conditions

|                  |                                                          | MIN  | MAX  | UNIT |
|------------------|----------------------------------------------------------|------|------|------|
| V <sub>CC1</sub> | Supply Voltage, Side 1, 1.8-V operation                  | 1.71 | 1.89 | V    |
|                  | Supply Voltage, Side 1, 2.5-V, 3.3-V and 5.5-V operation | 2.25 | 5.5  | V    |
| V <sub>CC2</sub> | Supply Voltage, Side 2                                   | 4.5  | 5.5  | V    |
| T <sub>A</sub>   | Operating ambient temperature                            | -40  | 125  | °C   |

## 6.5 Thermal Information

| THERMAL METRIC <sup>(1)</sup> |                                              | ISO1042-Q1 |            | UNIT |
|-------------------------------|----------------------------------------------|------------|------------|------|
|                               |                                              | DW (SOIC)  | DWV (SOIC) |      |
|                               |                                              | 16 PINS    | 8 PINS     |      |
| $R_{\theta JA}$               | Junction-to-ambient thermal resistance       | 69.9       | 100        | °C/W |
| $R_{\theta JC(top)}$          | Junction-to-case (top) thermal resistance    | 31.8       | 40.8       | °C/W |
| $R_{\theta JB}$               | Junction-to-board thermal resistance         | 29.0       | 51.8       | °C/W |
| $\Psi_{JT}$                   | Junction-to-top characterization parameter   | 13.2       | 16.8       | °C/W |
| $\Psi_{JB}$                   | Junction-to-board characterization parameter | 28.6       | 49.8       | °C/W |
| $R_{\theta JC(bot)}$          | Junction-to-case (bottom) thermal resistance | -          | -          | °C/W |

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.6 Power Ratings

| PARAMETER |                                        | TEST CONDITIONS                                                                                                                                                                                                                       | MIN | TYP | MAX | UNIT |
|-----------|----------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----|-----|-----|------|
| $P_D$     | Maximum power dissipation (both sides) | See <a href="#">Figure 7-3</a> , $V_{CC1} = V_{CC2} = 5.5\text{ V}$ , $T_J = 150^\circ\text{C}$ , $R_L = 50\ \Omega$ , A repetitive pattern on TXD with 1 ms time period, 990 $\mu\text{s}$ LOW time, and 10 $\mu\text{s}$ HIGH time. |     |     | 385 | mW   |
| $P_{D1}$  | Maximum power dissipation (side-1)     | See <a href="#">Figure 7-5</a> , $V_{CC1} = V_{CC2} = 5.5\text{ V}$ , $T_J = 150^\circ\text{C}$ , $R_L = 50\ \Omega$ , Input a 2-V pk-pk 2.5-MHz 50% duty cycle differential square wave on CANH-CANL                                 |     |     | 25  | mW   |
| $P_{D2}$  | Maximum power dissipation (side-2)     | See <a href="#">Figure 7-3</a> , $V_{CC1} = V_{CC2} = 5.5\text{ V}$ , $T_J = 150^\circ\text{C}$ , $R_L = 50\ \Omega$ , A repetitive pattern on TXD with 1 ms time period, 990 $\mu\text{s}$ LOW time, and 10 $\mu\text{s}$ HIGH time. |     |     | 360 | mW   |

## 6.7 Insulation Specifications

| PARAMETER                                |                                                            | TEST CONDITIONS                                                                                                                                                                                                                                                                                                 | SPECIFICATIONS     |                    | UNIT             |
|------------------------------------------|------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------|--------------------|------------------|
|                                          |                                                            |                                                                                                                                                                                                                                                                                                                 | DW-16              | DWV-8              |                  |
| IEC 60664-1                              |                                                            |                                                                                                                                                                                                                                                                                                                 |                    |                    |                  |
| CLR                                      | External clearance <sup>(1)</sup>                          | Side 1 to side 2 distance through air                                                                                                                                                                                                                                                                           | >8                 | >8.5               | mm               |
| CPG                                      | External Creepage <sup>(1)</sup>                           | Side 1 to side 2 distance across package surface                                                                                                                                                                                                                                                                | >8                 | >8.5               | mm               |
| DTI                                      | Distance through the insulation                            | Minimum internal gap (internal clearance)                                                                                                                                                                                                                                                                       | >17                | >17                | μm               |
| CTI                                      | Comparative tracking index                                 | IEC 60112; UL 746A                                                                                                                                                                                                                                                                                              | >600               | >600               | V                |
|                                          | Material Group                                             | According to IEC 60664-1                                                                                                                                                                                                                                                                                        | I                  | I                  |                  |
|                                          | Overvoltage category                                       | Rated mains voltage ≤ 600 V <sub>RMS</sub>                                                                                                                                                                                                                                                                      | I-IV               | I-IV               |                  |
|                                          |                                                            | Rated mains voltage ≤ 1000 V <sub>RMS</sub>                                                                                                                                                                                                                                                                     | I-III              | I-III              |                  |
| DIN VDE V 0884-11:2017-01 <sup>(2)</sup> |                                                            |                                                                                                                                                                                                                                                                                                                 |                    |                    |                  |
| V <sub>IORM</sub>                        | Maximum repetitive peak isolation voltage                  | AC voltage (bipolar)                                                                                                                                                                                                                                                                                            | 1500               | 1500               | V <sub>PK</sub>  |
| V <sub>IOWM</sub>                        | Maximum isolation working voltage                          | AC voltage (sine wave); time-dependent dielectric breakdown (TDDb) test;                                                                                                                                                                                                                                        | 1060               | 1060               | V <sub>RMS</sub> |
|                                          |                                                            | DC voltage                                                                                                                                                                                                                                                                                                      | 1500               | 1500               | V <sub>DC</sub>  |
| V <sub>IOTM</sub>                        | Maximum transient isolation voltage                        | V <sub>TEST</sub> = V <sub>IOTM</sub> , t = 60 s (qualification); V <sub>TEST</sub> = 1.2 × V <sub>IOTM</sub> , t = 1 s (100% production)                                                                                                                                                                       | 7071               | 7071               | V <sub>PK</sub>  |
| V <sub>IOSM</sub>                        | Maximum surge isolation voltage ISO1042-Q1 <sup>(3)</sup>  | Test method per IEC 62368-1, 1.2/50 μs waveform, V <sub>TEST</sub> = 1.6 × V <sub>IOSM</sub> = 10000 V <sub>PK</sub> (qualification)                                                                                                                                                                            | 6250               | 6250               | V <sub>PK</sub>  |
|                                          | Maximum surge isolation voltage ISO1042B-Q1 <sup>(3)</sup> | Test method per IEC 62368-1, 1.2/50 μs waveform, V <sub>TEST</sub> = 1.3 × V <sub>IOSM</sub> = 6000 V <sub>PK</sub> (qualification)                                                                                                                                                                             | 4615               | 4615               | V <sub>PK</sub>  |
| q <sub>pd</sub>                          | Apparent charge <sup>(4)</sup>                             | Method a: After I/O safety test subgroup 2/3, V <sub>ini</sub> = V <sub>IOTM</sub> , t <sub>ini</sub> = 60 s; V <sub>pd(m)</sub> = 1.2 × V <sub>IORM</sub> , t <sub>m</sub> = 10 s                                                                                                                              | ≤ 5                | ≤ 5                | pC               |
|                                          |                                                            | Method a: After environmental tests subgroup 1, V <sub>ini</sub> = V <sub>IOTM</sub> , t <sub>ini</sub> = 60 s; ISO1042-Q1: V <sub>pd(m)</sub> = 1.6 × V <sub>IORM</sub> , t <sub>m</sub> = 10 s ISO1042B-Q1: V <sub>pd(m)</sub> = 1.2 × V <sub>IORM</sub> , t <sub>m</sub> = 10 s                              | ≤ 5                | ≤ 5                |                  |
|                                          |                                                            | Method b1: At routine test (100% production) and preconditioning (type test), V <sub>ini</sub> = V <sub>IOTM</sub> , t <sub>ini</sub> = 1 s; ISO1042-Q1: V <sub>pd(m)</sub> = 1.875 × V <sub>IORM</sub> , t <sub>m</sub> = 1 s ISO1042B-Q1: V <sub>pd(m)</sub> = 1.5 × V <sub>IORM</sub> , t <sub>m</sub> = 1 s | ≤ 5                | ≤ 5                |                  |
| C <sub>IO</sub>                          | Barrier capacitance, input to output <sup>(5)</sup>        | V <sub>IO</sub> = 0.4 × sin (2 π ft), f = 1 MHz                                                                                                                                                                                                                                                                 | 1                  | 1                  | pF               |
| R <sub>IO</sub>                          | Insulation resistance, input to output <sup>(5)</sup>      | V <sub>IO</sub> = 500 V, T <sub>A</sub> = 25°C                                                                                                                                                                                                                                                                  | > 10 <sup>12</sup> | > 10 <sup>12</sup> | Ω                |
|                                          |                                                            | V <sub>IO</sub> = 500 V, 100°C ≤ T <sub>A</sub> ≤ 150°C                                                                                                                                                                                                                                                         | > 10 <sup>11</sup> | > 10 <sup>11</sup> |                  |
|                                          |                                                            | V <sub>IO</sub> = 500 V at T <sub>S</sub> = 150°C                                                                                                                                                                                                                                                               | > 10 <sup>9</sup>  | > 10 <sup>9</sup>  |                  |
|                                          | Pollution degree                                           |                                                                                                                                                                                                                                                                                                                 | 2                  | 2                  |                  |
|                                          | Climatic category                                          |                                                                                                                                                                                                                                                                                                                 | 40/125/21          | 40/125/21          |                  |
| UL 1577                                  |                                                            |                                                                                                                                                                                                                                                                                                                 |                    |                    |                  |
| V <sub>ISO</sub>                         | Withstand isolation voltage                                | V <sub>TEST</sub> = V <sub>ISO</sub> , t = 60 s (qualification); V <sub>TEST</sub> = 1.2 × V <sub>ISO</sub> , t = 1 s (100% production)                                                                                                                                                                         | 5000               | 5000               | V <sub>RMS</sub> |

- (1) Creepage and clearance requirements should be applied according to the specific equipment isolation standards of an application. Care should be taken to maintain the creepage and clearance distance of a board design to ensure that the mounting pads of the isolator on the printed-circuit board do not reduce this distance. Creepage and clearance on a printed-circuit board become equal in certain cases. Techniques such as inserting grooves, ribs, or both on a printed circuit board are used to help increase these specifications.

## ISO1042-Q1

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- (2) ISO1042-Q1 is suitable for *safe electrical insulation* and ISO1042B-Q1 is suitable for *basic electrical insulation* only within the safety ratings. Compliance with the safety ratings shall be ensured by means of suitable protective circuits.
- (3) Testing is carried out in air or oil to determine the intrinsic surge immunity of the isolation barrier.
- (4) Apparent charge is electrical discharge caused by a partial discharge (pd).
- (5) All pins on each side of the barrier tied together creating a two-pin device.

## 6.8 Safety-Related Certifications

| VDE                                                                                                                                                                                                                                                             | CSA                                                                                                                                                                                                                                                                                                                                                                                                                                   | UL                                                     | CQC                                                                                                      | TUV                                                                                                                                                                                                                                                                                                             |
|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------|----------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Certified according to DIN VDE V 0884-11:2017- 01                                                                                                                                                                                                               | Certified according to IEC 60950-1, IEC 62368-1 and IEC 60601-1                                                                                                                                                                                                                                                                                                                                                                       | Recognized under UL 1577 Component Recognition Program | Certified according to GB4943.1-2011                                                                     | Certified according to EN 61010-1:2010/A1:2019, EN 60950-1:2006/A2:2013 and EN 62368-1:2014                                                                                                                                                                                                                     |
| Maximum transient isolation voltage, 7071 V <sub>PK</sub> ;<br>Maximum repetitive peak isolation voltage, 1500 V <sub>PK</sub> ;<br>Maximum surge isolation voltage, ISO1042-Q1: 6250 V <sub>PK</sub> (Reinforced)<br>ISO1042B-Q1: 4615 V <sub>PK</sub> (Basic) | CSA 60950-1-07+A1+A2, IEC 60950-1 2 <sup>nd</sup> Ed.+A1+A2 and IEC 62368-1 2 <sup>nd</sup> Ed., for pollution degree 2, material group I<br>ISO1042-Q1: 800 V <sub>RMS</sub> reinforced isolation<br>ISO1042B-Q1: 1060 V <sub>RMS</sub> basic isolation<br>-----<br>CSA 60601- 1:14 and IEC 60601-1 Ed. 3.1+A1, ISO1042-Q1: 2 MOPP (Means of Patient Protection) 250 V <sub>RMS</sub> (354 V <sub>PK</sub> ) maximum working voltage | Single protection, 5000 V <sub>RMS</sub>               | Reinforced insulation, Altitude ≤ 5000 m, Tropical Climate, 700 V <sub>RMS</sub> maximum working voltage | EN 61010-1:2010 / A1:2019<br>ISO1042-Q1: 600 V <sub>RMS</sub> reinforced isolation<br>ISO1042B-Q1: 1000 V <sub>RMS</sub> basic isolation<br>-----<br>EN 60950-1:2006/A2:2013 and EN 62368-1:2014<br>ISO1042-Q1: 800 V <sub>RMS</sub> reinforced isolation<br>ISO1042B-Q1: 1060 V <sub>RMS</sub> basic isolation |
| Certificates:<br>Reinforced: 40040142<br>Basic: 40047657                                                                                                                                                                                                        | Master contract number: 220991                                                                                                                                                                                                                                                                                                                                                                                                        | File number: E181974                                   | Certificate:<br>CQC15001121716 (DW-16)<br>CQC18001199096 (DWV-8)                                         | Client ID number: 77311                                                                                                                                                                                                                                                                                         |

## 6.9 Safety Limiting Values

Safety limiting<sup>(1)</sup> intends to minimize potential damage to the isolation barrier upon failure of input or output circuitry.

| PARAMETER            |                                         | TEST CONDITIONS                                                                                                                | MIN | TYP | MAX  | UNIT |
|----------------------|-----------------------------------------|--------------------------------------------------------------------------------------------------------------------------------|-----|-----|------|------|
| <b>DW-16 PACKAGE</b> |                                         |                                                                                                                                |     |     |      |      |
| I <sub>S</sub>       | Safety input, output, or supply current | R <sub>θJA</sub> = 69.9°C/W, V <sub>I</sub> = 5.5 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-1</a>  |     |     | 325  | mA   |
|                      |                                         | R <sub>θJA</sub> = 69.9°C/W, V <sub>I</sub> = 3.6 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-1</a>  |     |     | 496  |      |
|                      |                                         | R <sub>θJA</sub> = 69.9°C/W, V <sub>I</sub> = 2.75 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-1</a> |     |     | 650  |      |
|                      |                                         | R <sub>θJA</sub> = 69.9°C/W, V <sub>I</sub> = 1.89 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-1</a> |     |     | 946  |      |
| P <sub>S</sub>       | Safety input, output, or total power    | R <sub>θJA</sub> = 69.9°C/W, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-3</a>                          |     |     | 1788 | mW   |
| T <sub>S</sub>       | Maximum safety temperature              |                                                                                                                                |     |     | 150  | °C   |
| <b>DWV-8 PACKAGE</b> |                                         |                                                                                                                                |     |     |      |      |
| I <sub>S</sub>       | Safety input, output, or supply current | R <sub>θJA</sub> = 100°C/W, V <sub>I</sub> = 5.5 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-2</a>   |     |     | 227  | mA   |
|                      |                                         | R <sub>θJA</sub> = 100°C/W, V <sub>I</sub> = 3.6 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-2</a>   |     |     | 347  |      |
|                      |                                         | R <sub>θJA</sub> = 100°C/W, V <sub>I</sub> = 2.75 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-2</a>  |     |     | 454  |      |
|                      |                                         | R <sub>θJA</sub> = 100°C/W, V <sub>I</sub> = 1.89 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-2</a>  |     |     | 661  |      |
| P <sub>S</sub>       | Safety input, output, or total power    | R <sub>θJA</sub> = 100°C/W, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-4</a>                           |     |     | 1250 | mW   |
| T <sub>S</sub>       | Maximum safety temperature              |                                                                                                                                |     |     | 150  | °C   |

- (1) The maximum safety temperature, T<sub>S</sub>, has the same value as the maximum junction temperature, T<sub>J</sub>, specified for the device. The I<sub>S</sub> and P<sub>S</sub> parameters represent the safety current and safety power respectively. The maximum limits of I<sub>S</sub> and P<sub>S</sub> should not be exceeded. These limits vary with the ambient temperature, T<sub>A</sub>.

The junction-to-air thermal resistance,  $R_{\theta JA}$ , in the table is that of a device installed on a high-K test board for leaded surface-mount packages. Use these equations to calculate the value for each parameter:

$T_J = T_A + R_{\theta JA} \times P$ , where  $P$  is the power dissipated in the device.

$T_{J(max)} = T_S = T_A + R_{\theta JA} \times P_S$ , where  $T_{J(max)}$  is the maximum allowed junction temperature.

$P_S = I_S \times V_I$ , where  $V_I$  is the maximum input voltage.

## 6.10 Electrical Characteristics - DC Specification

Over recommended operating conditions (unless otherwise noted)

| PARAMETER                          |                                                              | TEST CONDITIONS                                                             | MIN                  | TYP    | MAX  | UNIT |
|------------------------------------|--------------------------------------------------------------|-----------------------------------------------------------------------------|----------------------|--------|------|------|
| SUPPLY CHARACTERISTICS             |                                                              |                                                                             |                      |        |      |      |
| I <sub>CC1</sub>                   | Supply current Side 1                                        | V <sub>CC1</sub> = 1.71 V to 1.89 V, TXD = 0 V, bus dominant                |                      | 2.3    | 3.5  | mA   |
|                                    |                                                              | V <sub>CC1</sub> = 2.25 V to 5.5 V, TXD = 0 V, bus dominant                 |                      | 2.4    | 3.5  | mA   |
|                                    |                                                              | V <sub>CC1</sub> = 1.71 V to 1.89 V, TXD = V <sub>CC1</sub> , bus recessive |                      | 1.2    | 2.1  | mA   |
|                                    |                                                              | V <sub>CC1</sub> = 2.25 V to 5.5 V, TXD = V <sub>CC1</sub> , bus recessive  |                      | 1.3    | 2.1  | mA   |
| I <sub>CC2</sub>                   | Supply current Side 2                                        | TXD = 0 V, bus dominant, R <sub>L</sub> = 60 Ω                              |                      | 43     | 73.4 | mA   |
|                                    |                                                              | TXD = V <sub>CC1</sub> , bus recessive, R <sub>L</sub> = 60 Ω               |                      | 2.8    | 4.1  | mA   |
| UV <sub>VCC1</sub>                 | Rising under voltage detection, Side 1                       |                                                                             |                      |        | 1.7  | V    |
| UV <sub>VCC1</sub>                 | Falling under voltage detection, Side 1                      |                                                                             | 1.0                  |        |      | V    |
| V <sub>HYS(UVC C1)</sub>           | Hysterisis voltage on V <sub>CC1</sub> undervoltage lock-out |                                                                             | 75                   | 125    |      | mV   |
| UV <sub>VCC2</sub>                 | Rising under voltage detection, side 2                       |                                                                             |                      | 4.2    | 4.45 | V    |
| UV <sub>VCC2</sub>                 | Falling under voltage detection, side 2                      |                                                                             | 3.8                  | 4.0    | 4.25 | V    |
| V <sub>HYS(UVC C2)</sub>           | Hysterisis voltage on V <sub>CC2</sub> undervoltage lock-out |                                                                             |                      | 200    |      | mV   |
| TXD TERMINAL                       |                                                              |                                                                             |                      |        |      |      |
| V <sub>IH</sub>                    | High level input voltage                                     |                                                                             | 0.7×V <sub>CC1</sub> |        |      | V    |
| V <sub>IL</sub>                    | Low level input voltage                                      |                                                                             | 0.3×V <sub>CC1</sub> |        |      | V    |
| I <sub>IH</sub>                    | High level input leakage current                             | TXD = V <sub>CC1</sub>                                                      | 1                    |        |      | uA   |
| I <sub>IL</sub>                    | Low level input leakage current                              | TXD = 0V                                                                    | -20                  |        |      | uA   |
| C <sub>I</sub>                     | Input capacitance                                            | VIN = 0.4 x sin(2 x π x 1E+6 x t) + 2.5 V, V <sub>CC1</sub> = 5 V           | 3                    |        |      | pF   |
| RXD TERMINAL                       |                                                              |                                                                             |                      |        |      |      |
| V <sub>OH</sub> - V <sub>CC1</sub> | High level output voltage                                    | See 图 7-4, I <sub>O</sub> = -4 mA for 4.5 V ≤ V <sub>CC1</sub> ≤ 5.5 V      | -0.4                 | -0.2   |      | V    |
|                                    |                                                              | See 图 7-4, I <sub>O</sub> = -2 mA for 3.0 V ≤ V <sub>CC1</sub> ≤ 3.6 V      | -0.2                 | -0.07  |      | V    |
|                                    |                                                              | See 图 7-4, I <sub>O</sub> = -1 mA for 2.25 V ≤ V <sub>CC1</sub> ≤ 2.75 V    | -0.1                 | -0.04  |      | V    |
|                                    |                                                              | See 图 7-4, I <sub>O</sub> = -1 mA for 1.71 V ≤ V <sub>CC1</sub> ≤ 1.89 V    | -0.1                 | -0.045 |      | V    |
| V <sub>OL</sub>                    | Low level output voltage                                     | See 图 7-4, I <sub>O</sub> = 4 mA for 4.5 V ≤ V <sub>CC1</sub> ≤ 5.5 V       |                      | 0.2    | 0.4  | V    |
|                                    |                                                              | See 图 7-4, I <sub>O</sub> = 2 mA for 3.0 V ≤ V <sub>CC1</sub> ≤ 3.6 V       |                      | 0.07   | 0.2  | V    |
|                                    |                                                              | See 图 7-4, I <sub>O</sub> = 1 mA for 2.25 V ≤ V <sub>CC1</sub> ≤ 2.75 V     |                      | 0.035  | 0.1  | V    |
|                                    |                                                              | See 图 7-4, I <sub>O</sub> = 1 mA for 1.71 V ≤ V <sub>CC1</sub> ≤ 1.89 V     |                      | 0.04   | 0.1  | V    |
| DRIVER ELECTRICAL CHARACTERISTICS  |                                                              |                                                                             |                      |        |      |      |

Over recommended operating conditions (unless otherwise noted)

| PARAMETER                                  |                                                                                       | TEST CONDITIONS                                                                                    | MIN    | TYP                    | MAX    | UNIT |
|--------------------------------------------|---------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------|--------|------------------------|--------|------|
| V <sub>O(DOM)</sub>                        | Bus output voltage(Dominant), CANH                                                    | See 图 7-1 and 图 7-2, TXD = 0 V, 50 Ω ≤ R <sub>L</sub> ≤ 65 Ω, C <sub>L</sub> = open                | 2.75   |                        | 4.5    | V    |
|                                            | Bus output voltage(Dominant), CANL                                                    | See 图 7-1 and 图 7-2, TXD = 0 V, 50 Ω ≤ R <sub>L</sub> ≤ 65 Ω, C <sub>L</sub> = open                | 0.5    |                        | 2.25   | V    |
| V <sub>O(REC)</sub>                        | Bus output voltage(recessive), CANH and CANL                                          | See 图 7-1 and 图 7-2, TXD = V <sub>CC1</sub> , R <sub>L</sub> = open                                | 2.0    | 0.5 x V <sub>CC2</sub> | 3.0    | V    |
| V <sub>OD(DOM)</sub>                       | Differential output voltage, CANH-CANL (dominant)                                     | See 图 7-1 and 图 7-2, TXD = 0 V, 45 Ω ≤ R <sub>L</sub> ≤ 50 Ω, C <sub>L</sub> = open                | 1.4    |                        | 3.0    | V    |
|                                            | Differential output voltage, CANH-CANL (dominant)                                     | See 图 7-1 and 图 7-2, TXD = 0 V, 50 Ω ≤ R <sub>L</sub> ≤ 65 Ω, C <sub>L</sub> = open                | 1.5    |                        | 3.0    | V    |
|                                            | Differential output voltage, CANH-CANL (dominant)                                     | See 图 7-1 and 图 7-2, TXD = 0 V, R <sub>L</sub> = 2240 Ω, C <sub>L</sub> = open                     | 1.5    |                        | 5.0    | V    |
| V <sub>OD(REC)</sub>                       | Differential output voltage, CANH-CANL (recessive)                                    | See 图 7-1 and 图 7-2, TXD = V <sub>CC1</sub> , R <sub>L</sub> = 60 Ω, C <sub>L</sub> = open         | -120.0 |                        | 12.0   | mV   |
|                                            | Differential output voltage, CANH-CANL (recessive)                                    | See 图 7-1 and 图 7-2, TXD = V <sub>CC1</sub> , R <sub>L</sub> = open, C <sub>L</sub> = open         | -50.0  |                        | 50.0   | mV   |
| V <sub>SYM_DC</sub>                        | DC Output symmetry (V <sub>CC2</sub> - V <sub>O(CANH)</sub> - V <sub>O(CANL)</sub> )  | See 图 7-1 and 图 7-2, R <sub>L</sub> = 60 Ω, C <sub>L</sub> = open, TXD = V <sub>CC1</sub> or 0 V   | -400.0 |                        | 400.0  | mV   |
| I <sub>SO(SS_DO M)</sub>                   | Short circuit current steady state output current, dominant                           | See 图 7-9, V <sub>CANH</sub> = -5 V to 40 V, CANL = open, TXD = 0 V                                | -100.0 |                        |        | mA   |
|                                            |                                                                                       | See 图 7-9, V <sub>CANL</sub> = -5 V to 40 V, CANH = open, TXD = 0 V                                |        |                        | 100.0  | mA   |
| I <sub>SO(SS_RE C)</sub>                   | Short circuit current steady state output current, recessive                          | See 图 7-9, -27 V ≤ V <sub>BUS</sub> ≤ 32 V, V <sub>BUS</sub> = CANH = CANL, TXD = V <sub>CC1</sub> | -5.0   |                        | 5.0    | mA   |
| <b>RECEIVER ELECTRICAL CHARACTERISTICS</b> |                                                                                       |                                                                                                    |        |                        |        |      |
| V <sub>IT</sub>                            | Differential input threshold voltage                                                  | See 图 7-4 and 表 7-1,  V <sub>CM</sub>   ≤ 20 V                                                     | 500.0  |                        | 900.0  | mV   |
|                                            | Differential input threshold voltage                                                  | See 图 7-4 and 表 7-1, 20 V ≤  V <sub>CM</sub>   ≤ 30 V                                              | 400.0  |                        | 1000.0 |      |
| V <sub>HYS</sub>                           | Hysteresis voltage for differential input threshold                                   | See 图 7-4 and 表 7-1                                                                                |        | 120                    |        |      |
| V <sub>CM</sub>                            | Input common mode range                                                               | See 图 7-4 and 表 7-1                                                                                | -30.0  |                        | 30.0   | V    |
| I <sub>OFF(LKG)</sub>                      | Power-off bus input leakage current                                                   | CANH = CANL = 5 V, V <sub>CC2</sub> to GND via 0 Ω and 47 k Ω resistor                             |        |                        | 4.8    | uA   |
| C <sub>I</sub>                             | Input capacitance to ground (CANH or CANL)                                            | TXD = V <sub>CC1</sub>                                                                             |        | 24.0                   | 30     | pF   |
| C <sub>ID</sub>                            | Differential input capacitance (CANH-CANL)                                            | TXD = V <sub>CC1</sub>                                                                             |        | 12.0                   | 15     | pF   |
| R <sub>ID</sub>                            | Differential input resistance                                                         | TXD = V <sub>CC1</sub> ; -30 V ≤ V <sub>CM</sub> ≤ +30 V                                           | 30.0   |                        | 80.0   | k Ω  |
| R <sub>IN</sub>                            | Input resistance (CANH or CANL)                                                       | TXD = V <sub>CC1</sub> ; -30 V ≤ V <sub>CM</sub> ≤ +30 V                                           | 15.0   |                        | 40.0   | k Ω  |
| R <sub>IN(M)</sub>                         | Input resistance matching: (1 - R <sub>IN(CANH)</sub> /R <sub>IN(CANL)</sub> ) x 100% | V <sub>CANH</sub> = V <sub>CANL</sub> = 5 V                                                        | -2.0   |                        | 2.0    | %    |
| <b>THERMAL SHUTDOWN</b>                    |                                                                                       |                                                                                                    |        |                        |        |      |
| T <sub>TSD</sub>                           | Thermal shutdown temperature                                                          |                                                                                                    |        | 170                    |        | °C   |
| T <sub>TSD_HYS T</sub>                     | Thermal shutdown hysteresis                                                           |                                                                                                    |        | 5                      |        | °C   |

## 6.11 Switching Characteristics

Over recommended operating conditions (unless otherwise noted)

| PARAMETER                          |                                                                                                           | TEST CONDITIONS                                                                                                                                                             | MIN   | TYP | MAX   | UNIT  |
|------------------------------------|-----------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------|-----|-------|-------|
| DEVICE SWITCHING CHARACTERISTICS   |                                                                                                           |                                                                                                                                                                             |       |     |       |       |
| t <sub>PROP(LOOP1)</sub>           | Total loop delay, driver input TXD to receiver RXD, recessive to dominant                                 | See 图 7-6, R <sub>L</sub> = 60 Ω, C <sub>L</sub> = 100 pF, C <sub>L(RXD)</sub> = 15 pF; input rise/fall time (10% to 90%) on TXD = 1 ns; 1.71 V ≤ V <sub>CC1</sub> ≤ 1.89 V | 70    | 125 | 198.0 | ns    |
|                                    |                                                                                                           | See 图 7-6, R <sub>L</sub> = 60 Ω, C <sub>L</sub> = 100 pF, C <sub>L(RXD)</sub> = 15 pF; input rise/fall time (10% to 90%) on TXD = 1 ns; 2.25 V ≤ V <sub>CC1</sub> ≤ 5.5 V  | 70    | 122 | 192.0 | ns    |
| t <sub>PROP(LOOP2)</sub>           | Total loop delay, driver input TXD to receiver RXD, dominant to recessive                                 | See 图 7-6, R <sub>L</sub> = 60 Ω, C <sub>L</sub> = 100 pF, C <sub>L(RXD)</sub> = 15 pF; input rise/fall time (10% to 90%) on TXD = 1 ns; 1.71 V ≤ V <sub>CC1</sub> ≤ 1.89 V | 70    | 155 | 215.0 | ns    |
|                                    |                                                                                                           | See 图 7-6, R <sub>L</sub> = 60 Ω, C <sub>L</sub> = 100 pF, C <sub>L(RXD)</sub> = 15 pF; input rise/fall time (10% to 90%) on TXD = 1 ns; 2.25 V ≤ V <sub>CC1</sub> ≤ 5.5 V  | 70    | 152 | 215.0 | ns    |
| t <sub>UV_RE_ENABLE</sub>          | Re-enable time after Undervoltage event                                                                   | Time for device to return to normal operation from V <sub>CC1</sub> or V <sub>CC2</sub> under voltage event                                                                 |       |     | 300.0 | μs    |
| CMTI                               | Common mode transient immunity                                                                            | V <sub>CM</sub> = 1200 V <sub>PK</sub> , See 图 7-10                                                                                                                         | 85    | 100 |       | kV/μs |
| DRIVER SWITCHING CHARACTERISTICS   |                                                                                                           |                                                                                                                                                                             |       |     |       |       |
| t <sub>pHR</sub>                   | Propagation delay time, HIGH TXD to driver recessive                                                      | See 图 7-3, R <sub>L</sub> = 60 Ω and C <sub>L</sub> = 100 pF; input rise/fall time (10% to 90%) on TXD = 1 ns                                                               |       | 76  | 120   | ns    |
| t <sub>pLD</sub>                   | Propagation delay time, LOW TXD to driver dominant                                                        |                                                                                                                                                                             |       | 61  | 120   |       |
| t <sub>sk(p)</sub>                 | Pulse skew ( t <sub>pHR</sub> - t <sub>pLD</sub>  )                                                       |                                                                                                                                                                             |       | 14  |       |       |
| t <sub>R</sub>                     | Differential output signal rise time                                                                      |                                                                                                                                                                             |       | 45  |       |       |
| t <sub>F</sub>                     | Differential output signal fall time                                                                      |                                                                                                                                                                             |       | 45  |       |       |
| V <sub>SYM</sub>                   | Output symmetry (dominant or recessive) (V <sub>O(CANH)</sub> + V <sub>O(CANL)</sub> ) / V <sub>CC2</sub> | See 图 7-3 and 图 9-4 , R <sub>TERM</sub> = 60 Ω, C <sub>SPLIT</sub> = 4.7 nF, C <sub>L</sub> = open, R <sub>L</sub> = open, TXD = 250 kHz, 1 MHz                             | 0.9   |     | 1.1   | V/V   |
| t <sub>TXD_DTO</sub>               | Dominant time out                                                                                         | See 图 7-8, R <sub>L</sub> = 60 Ω and C <sub>L</sub> = open                                                                                                                  | 1.2   |     | 3.8   | ms    |
| RECEIVER SWITCHING CHARACTERISTICS |                                                                                                           |                                                                                                                                                                             |       |     |       |       |
| t <sub>pRH</sub>                   | Propagation delay time, bus recessive input to RXD high output                                            | See 图 7-5, C <sub>L(RXD)</sub> = 15 pF                                                                                                                                      |       | 75  | 130   | ns    |
| t <sub>pDL</sub>                   | Propogation delay time, bus dominant input to RXD low output                                              |                                                                                                                                                                             |       | 63  | 130   | ns    |
| t <sub>R</sub>                     | Output signal rise time(RXD)                                                                              |                                                                                                                                                                             |       | 1.4 |       | ns    |
| t <sub>F</sub>                     | Output signal fall time(RXD)                                                                              |                                                                                                                                                                             |       | 1.8 |       | ns    |
| FD TIMING PARAMETERS               |                                                                                                           |                                                                                                                                                                             |       |     |       |       |
| t <sub>BIT(BUS)</sub>              | Bit time on CAN bus output pins with t <sub>BIT(TXD)</sub> = 500 ns                                       | See 图 7-7, R <sub>L</sub> = 60 Ω, C <sub>L</sub> = 100 pF, C <sub>L(RXD)</sub> = 15 pF; input rise/fall time (10% to 90%) on TXD = 1 ns                                     | 435.0 |     | 530.0 | ns    |
|                                    | Bit time on CAN bus output pins with t <sub>BIT(TXD)</sub> = 200 ns                                       | See 图 7-7, R <sub>L</sub> = 60 Ω, C <sub>L</sub> = 100 pF, C <sub>L(RXD)</sub> = 15 pF; input rise/fall time (10% to 90%) on TXD = 1 ns                                     | 155.0 |     | 210.0 | ns    |

Over recommended operating conditions (unless otherwise noted)

| PARAMETER               |                                                                         | TEST CONDITIONS                                                                                                                                                                                                    | MIN   | TYP | MAX   | UNIT |
|-------------------------|-------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------|-----|-------|------|
| $t_{\text{BIT(RXD)}}$   | Bit time on RXD output pins with $t_{\text{BIT(TXD)}} = 500 \text{ ns}$ | See 图 7-7, $R_L = 60 \Omega$ , $C_L = 100 \text{ pF}$ , $C_{L(\text{RXD})} = 15 \text{ pF}$ ; input rise/fall time (10% to 90%) on TXD = 1 ns                                                                      | 400   |     | 550.0 | ns   |
|                         | Bit time on RXD output pins with $t_{\text{BIT(TXD)}} = 200 \text{ ns}$ | See 图 7-7, $R_L = 60 \Omega$ , $C_L = 100 \text{ pF}$ , $C_{L(\text{RXD})} = 15 \text{ pF}$ ; input rise/fall time (10% to 90%) on TXD = 1 ns                                                                      | 120.0 |     | 220.0 | ns   |
| $\Delta t_{\text{REC}}$ | Receiver timing symmetry with $t_{\text{BIT(TXD)}} = 500 \text{ ns}$    | See 图 7-7, $R_L = 60 \Omega$ , $C_L = 100 \text{ pF}$ , $C_{L(\text{RXD})} = 15 \text{ pF}$ ; input rise/fall time (10% to 90%) on TXD = 1 ns; $\Delta t_{\text{REC}} = t_{\text{BIT(RXD)}} - t_{\text{BIT(BUS)}}$ | -65.0 |     | 40.0  | ns   |
|                         | Receiver timing symmetry with $t_{\text{BIT(TXD)}} = 200 \text{ ns}$    | See 图 7-7, $R_L = 60 \Omega$ , $C_L = 100 \text{ pF}$ , $C_{L(\text{RXD})} = 15 \text{ pF}$ ; input rise/fall time (10% to 90%) on TXD = 1 ns; $\Delta t_{\text{REC}} = t_{\text{BIT(RXD)}} - t_{\text{BIT(BUS)}}$ | -45.0 |     | 15.0  | ns   |

## 6.12 Insulation Characteristics Curves

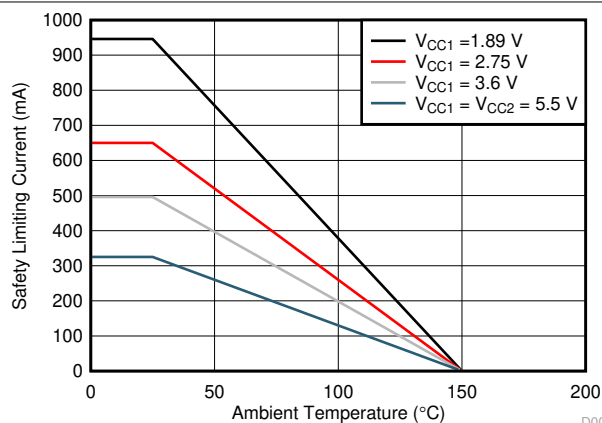


图 6-1. Thermal Derating Curve for Limiting Current per VDE for DW-16 Package

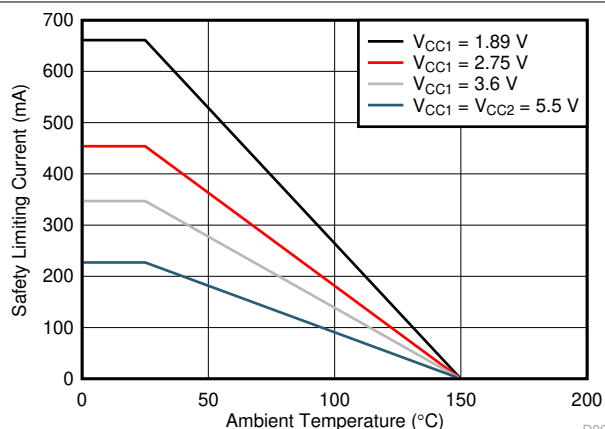


图 6-2. Thermal Derating Curve for Limiting Current per VDE for DWV-8 Package

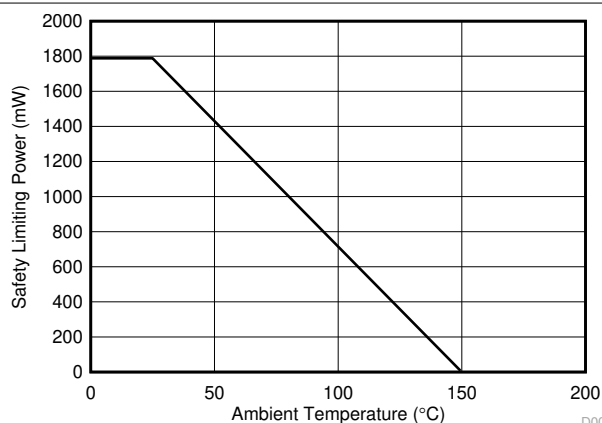


图 6-3. Thermal Derating Curve for Limiting Power per VDE for DW-16 Package

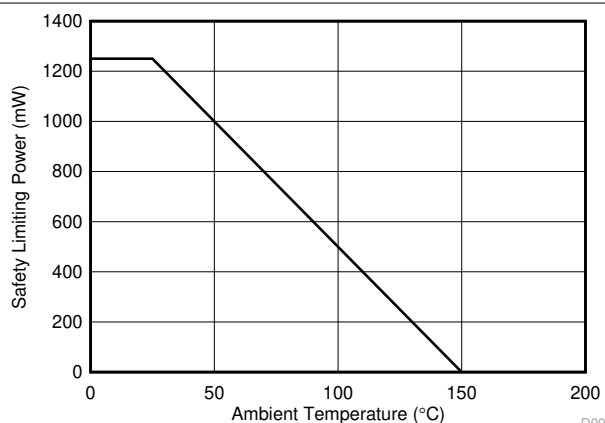


图 6-4. Thermal Derating Curve for Limiting Power per VDE for DWV-8 Package

## 6.13 Typical Characteristics

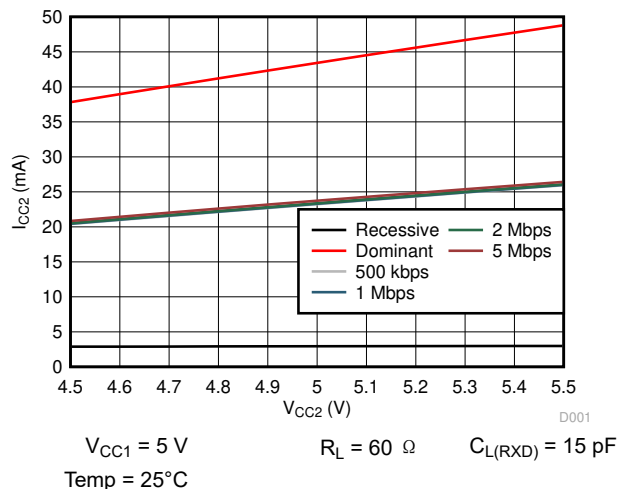


图 6-5.  $I_{CC2}$  vs  $V_{CC2}$  for Recessive, Dominant and Different CAN Datarates

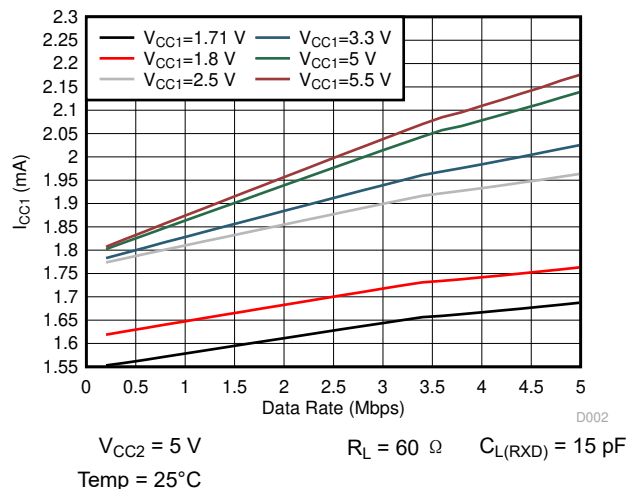


图 6-6.  $I_{CC1}$  vs Datarate

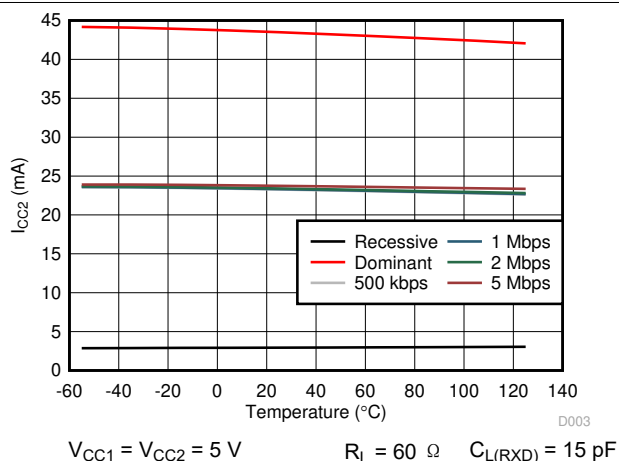


图 6-7.  $I_{CC2}$  vs Ambient Temperature for Recessive, Dominant and Different CAN Datarates

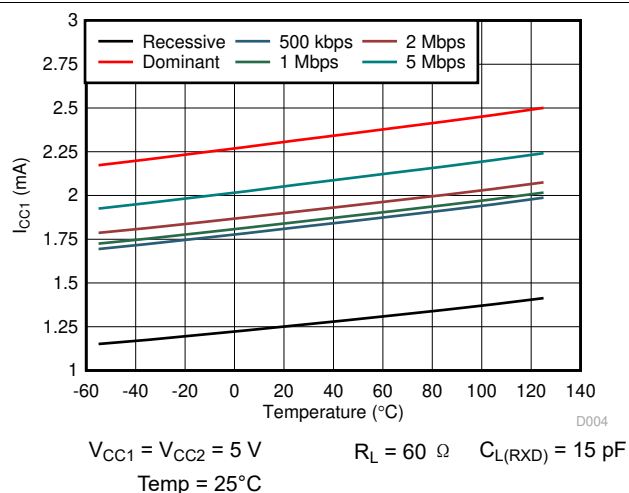


图 6-8. :  $I_{CC1}$  vs Ambient Temperature for Recessive, Dominant and Different CAN Datarates.

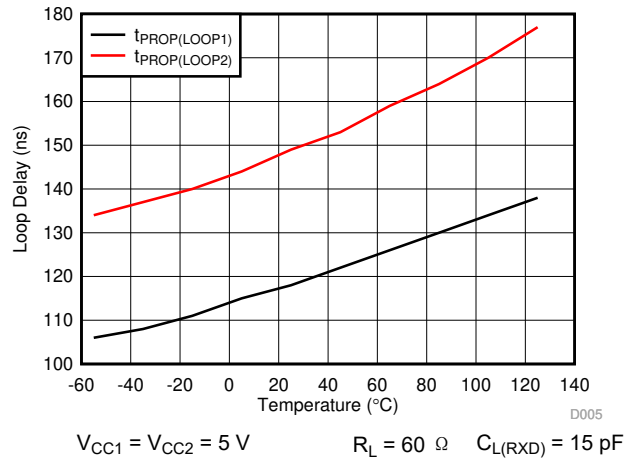


图 6-9. Loop Delay vs Ambient Temperature

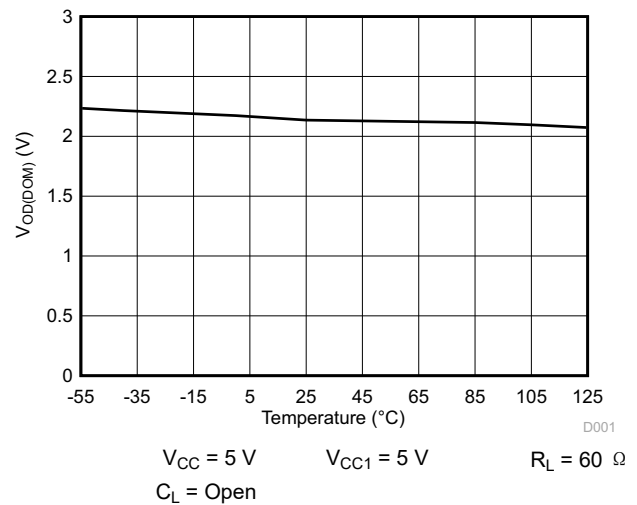


图 6-10.  $V_{OD(DOM)}$  Over Temperature

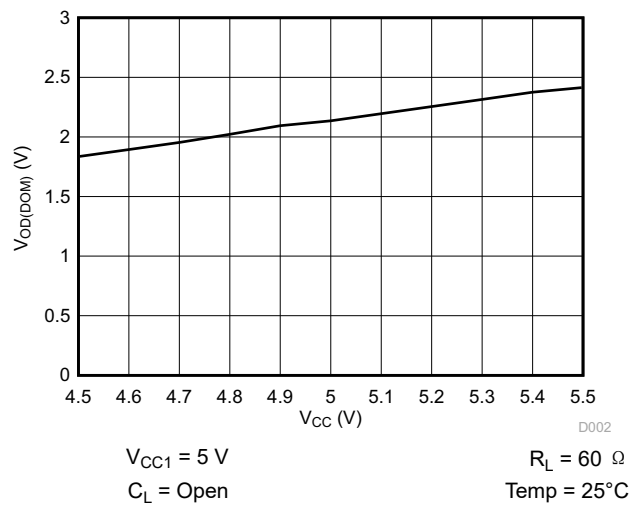


图 6-11.  $V_{OD(DOM)}$  Over  $V_{CC}$

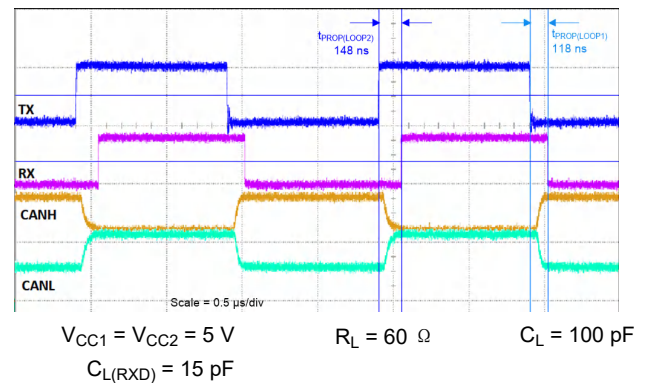


图 6-12. Typical TXD, RXD, CANH and CANL Waveforms at 1 Mbps

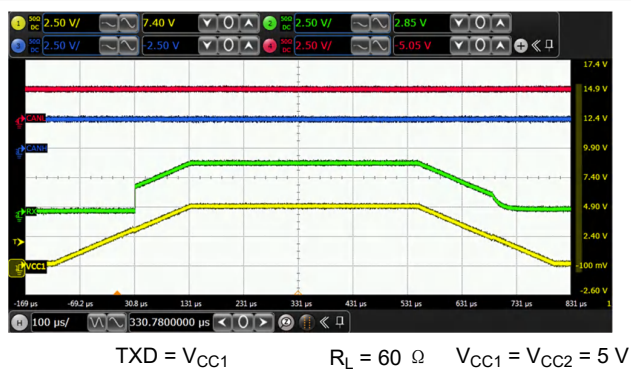


图 6-13. Glitch Free Power Up on  $V_{CC1}$  - CAN Bus Remains Recessive

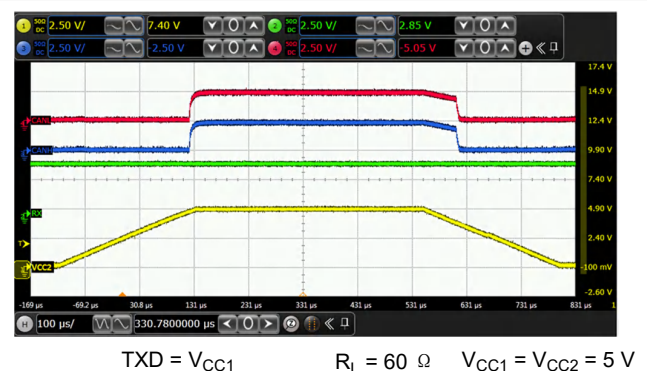
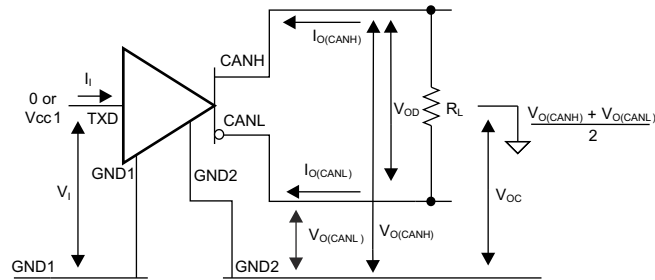


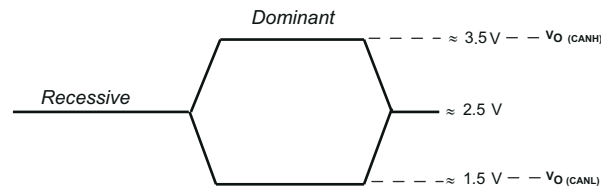
图 6-14. Glitch Free Power Up on  $V_{CC2}$  - CAN Bus Remains Recessive

## 7 Parameter Measurement Information

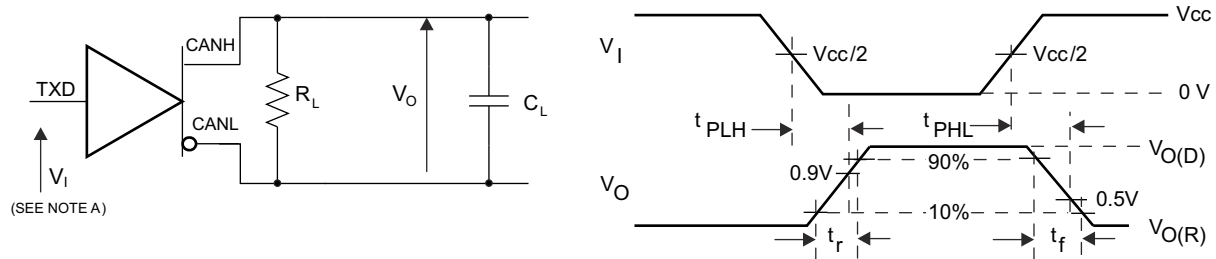
## 7.1 Test Circuits



**图 7-1. Driver Voltage, Current and Test Definitions**

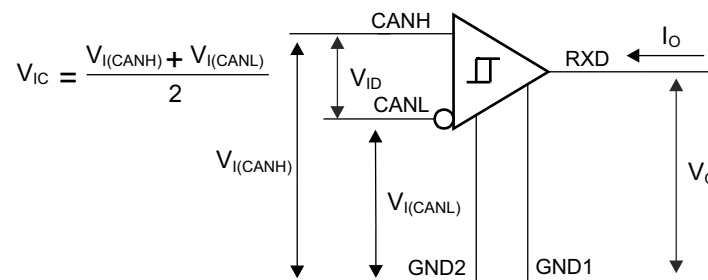


**图 7-2. Bus Logic State Voltage Definitions**

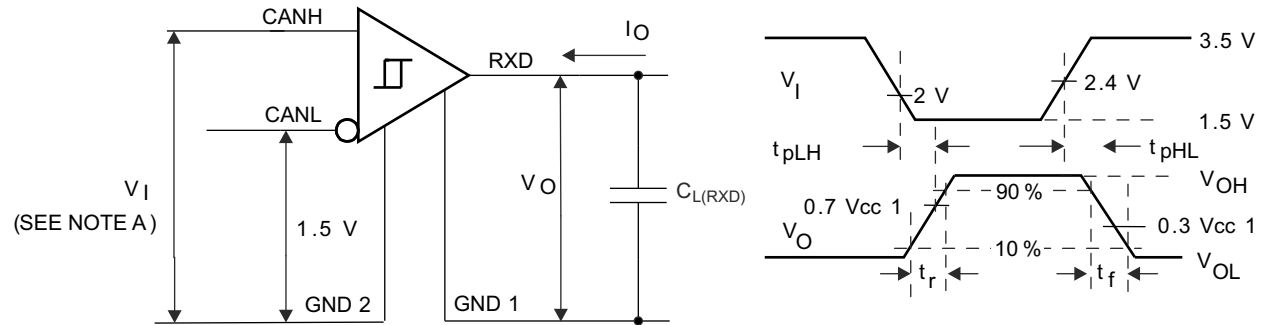


- A. The input pulse is supplied by a generator having the following characteristics:  $\text{PRR} \leq 125 \text{ kHz}$ , 50% duty cycle,  $t_r \leq 6 \text{ ns}$ ,  $t_f \leq 6 \text{ ns}$ ,  $Z_O = 50 \Omega$ .

**图 7-3. Driver Test Circuit and Voltage Waveforms**



### 图 7-4. Receiver Voltage and Current Definitions



- A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  125 kHz, 50% duty cycle,  $t_r \leq 6$  ns,  $t_f \leq 6$  ns,  $Z_O = 50 \Omega$ .

图 7-5. Receiver Test Circuit and Voltage Waveforms

表 7-1. Receiver Differential Input Voltage Threshold Test

| INPUT      |            |            | OUTPUT |          |
|------------|------------|------------|--------|----------|
| $V_{CANH}$ | $V_{CANL}$ | $ V_{ID} $ | RXD    |          |
| -29.5 V    | -30.5 V    | 1000 mV    | L      | $V_{OL}$ |
| 30.5 V     | 29.5 V     | 1000 mV    | L      |          |
| -19.55 V   | -20.45 V   | 900 mV     | L      |          |
| 20.45 V    | 19.55 V    | 900 mV     | L      |          |
| -19.75 V   | -20.25 V   | 500 mV     | H      | $V_{OH}$ |
| 20.25 V    | 19.75 V    | 500 mV     | H      |          |
| -29.8 V    | -30.2 V    | 400 mV     | H      |          |
| 30.2 V     | 29.8 V     | 400 mV     | H      |          |
| Open       | Open       | X          | H      |          |

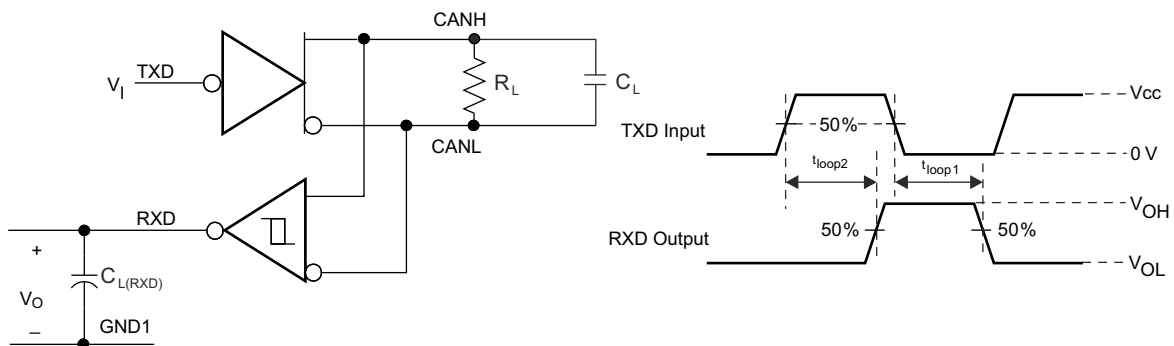


图 7-6.  $t_{LOOP}$  Test Circuit and Voltage Waveforms

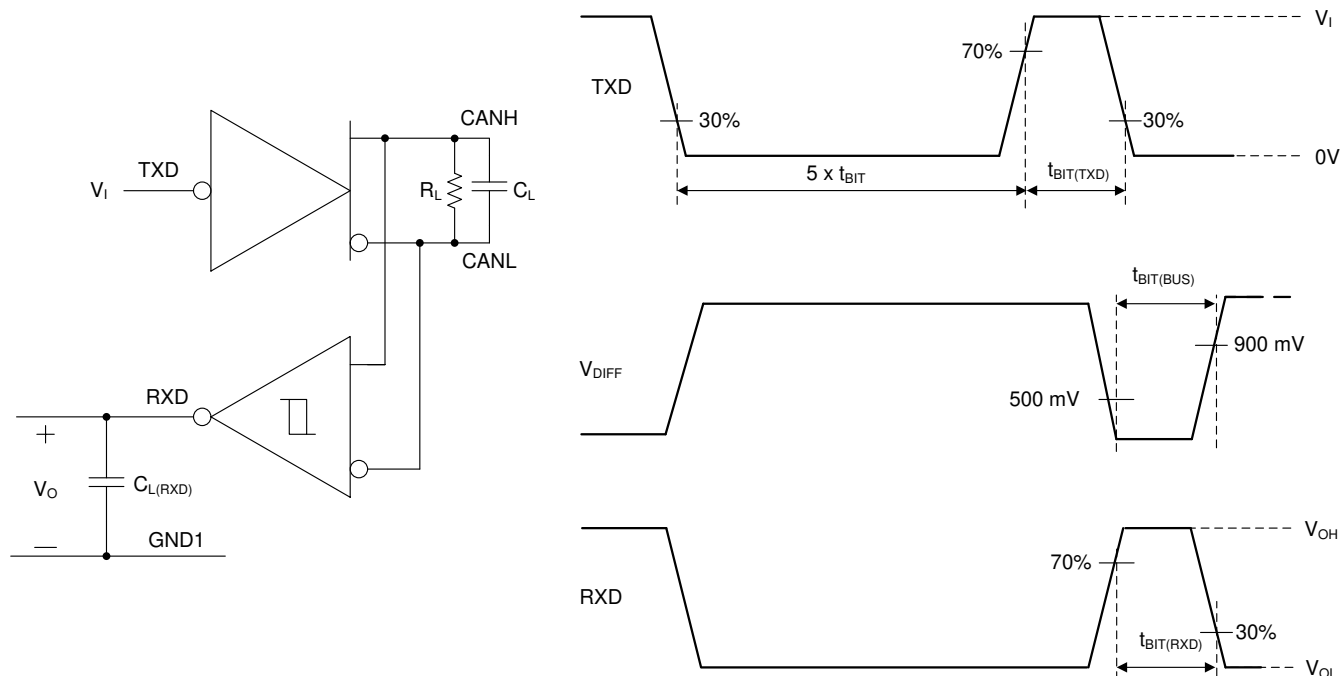
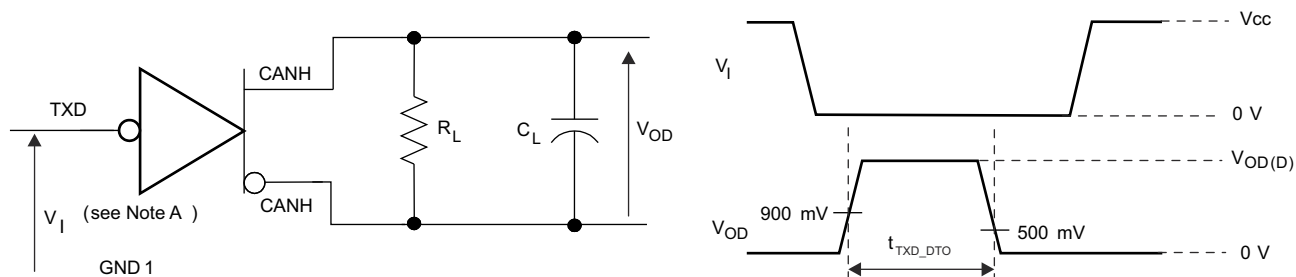


图 7-7. CAN FD Timing Parameter Measurement



A. The input pulse is supplied by a generator having the following characteristics:  $t_r \leq 6 \text{ ns}$ ,  $t_f \leq 6 \text{ ns}$ ,  $Z_O = 50 \Omega$ .

图 7-8. Dominant Time-out Test Circuit and Voltage Waveforms

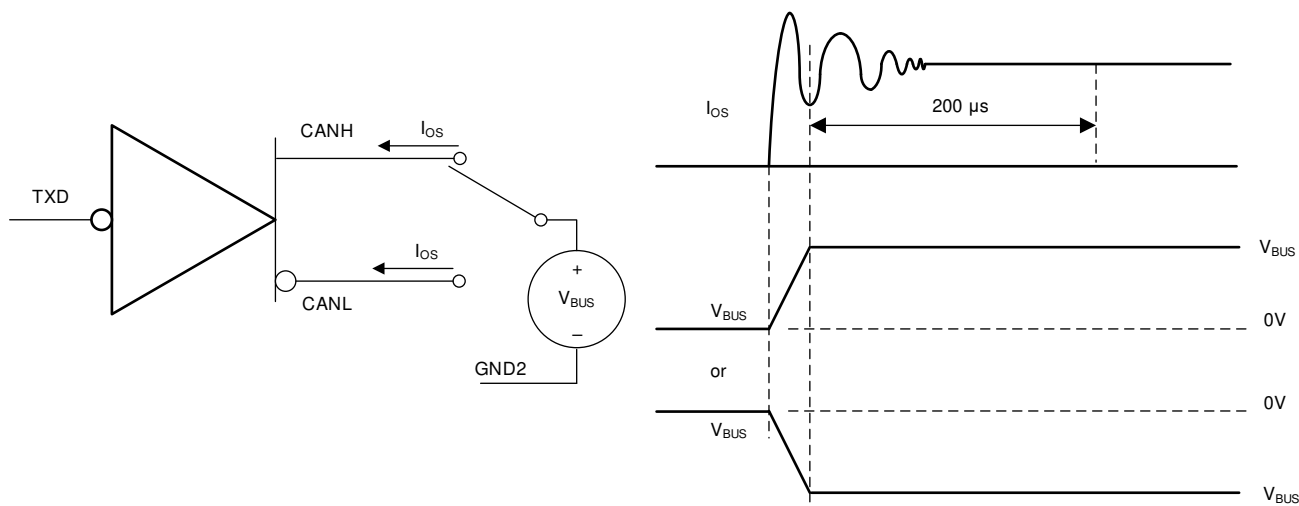


图 7-9. Driver Short-Circuit Current Test Circuit and Waveforms

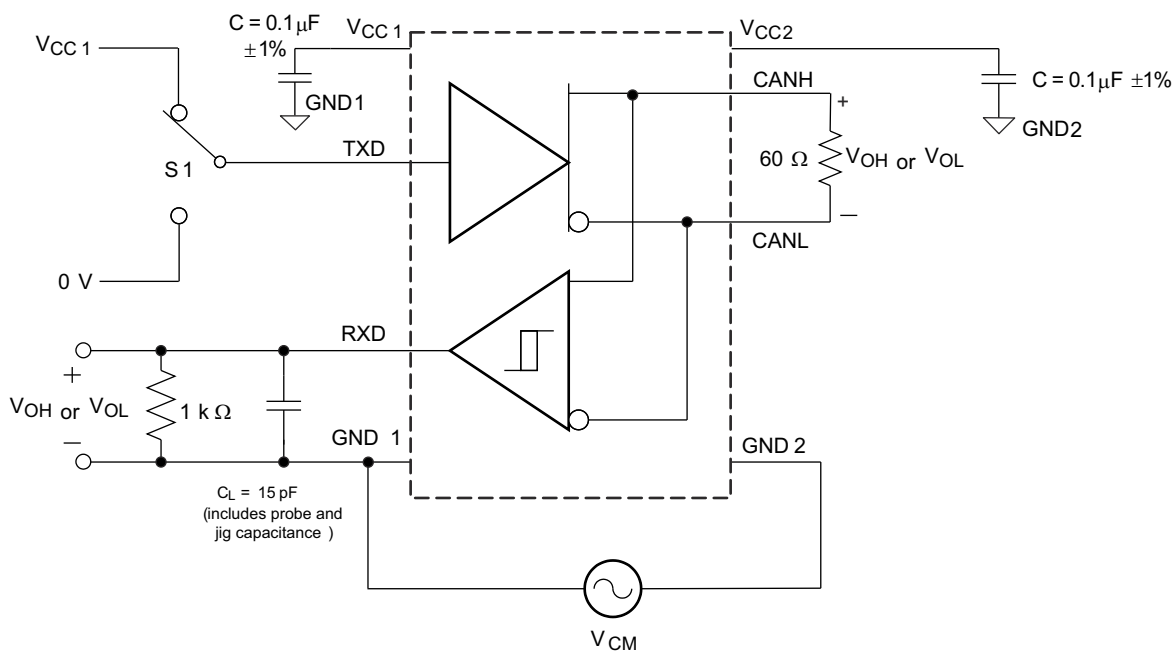


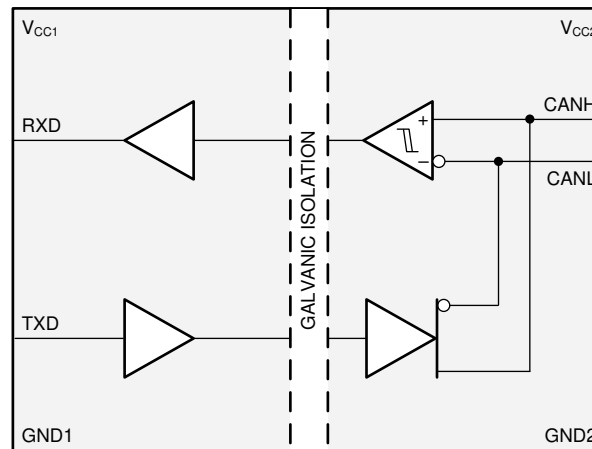
图 7-10. Common-Mode Transient Immunity Test Circuit

## 8 Detailed Description

### 8.1 Overview

The ISO1042-Q1 device is a digitally isolated CAN transceiver that offers  $\pm 70$ -V DC bus fault protection and  $\pm 30$ -V common-mode voltage range. The device supports up to 5-Mbps data rate in CAN FD mode allowing much faster transfer of payload compared to classic CAN. The ISO1042-Q1 device has an isolation withstand voltage of 5000 V<sub>RMS</sub> and is available in basic and reinforced isolation with a surge test voltage of 6 kV<sub>PK</sub> and 10 kV<sub>PK</sub> respectively. The device can operate from 1.8-V, 2.5-V, 3.3-V, and 5-V supplies on side 1 and a 5-V supply on side 2. This supply range is of particular advantage for applications operating in harsh industrial environments because the low voltage on side 1 enables the connection to low-voltage microcontrollers for power conservation, whereas the 5 V on side 2 maintains a high signal-to-noise ratio of the bus signals.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

#### 8.3.1 CAN Bus States

The CAN bus has two states during operation: *dominant* and *recessive*. A dominant bus state, equivalent to logic low, is when the bus is driven differentially by a driver. A recessive bus state is when the bus is biased to a common mode of  $V_{CC} / 2$  through the high-resistance internal input resistors of the receiver, equivalent to a logic high. The host microprocessor of the CAN node uses the TXD pin to drive the bus and receives data from the bus on the RXD pin. See [Figure 8-1](#) and [Figure 8-2](#).

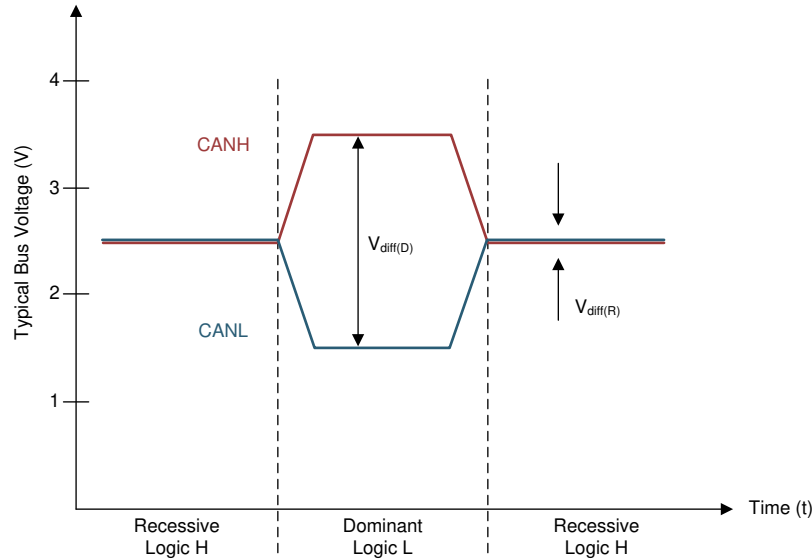


图 8-1. Bus States (Physical Bit Representation)

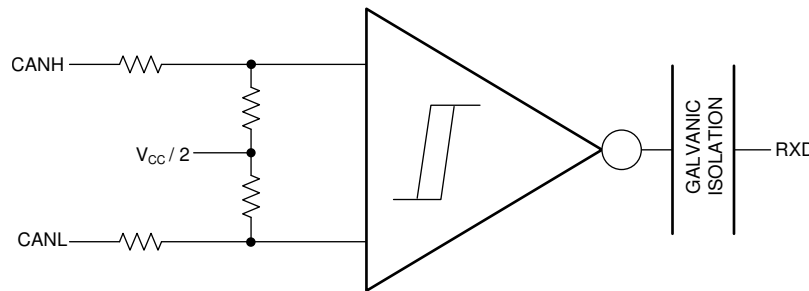


图 8-2. Simplified Recessive Common Mode Bias and Receiver

### 8.3.2 Digital Inputs and Outputs: TXD (Input) and RXD (Output)

The  $V_{CC1}$  supply for the isolated digital input and output side of the device can be supplied by 1.8-V, 2.5-V, 3.3-V, and 5-V supplies and therefore the digital inputs and outputs are 1.8-V, 2.5-V, 3.3-V, and 5-V compatible.

#### 备注

The TXD pin is very weakly internally pulled up to  $V_{CC1}$ . An external pullup resistor should be used to make sure that the TXD pin is biased to recessive (high) level to avoid issues on the bus if the microprocessor does not control the pin and the TXD pin floats. The TXD pullup strength and CAN bit timing require special consideration when the device is used with an open-drain TXD output on the CAN controller of the microprocessor. An adequate external pullup resistor must be used to make sure that the TXD output of the microprocessor maintains adequate bit timing input to the input on the transceiver.

### 8.3.3 Protection Features

#### 8.3.3.1 TXD Dominant Timeout (DTO)

The TXD DTO circuit prevents the transceiver from blocking network communication in the event of a hardware or software failure where the TXD pin is held dominant longer than the timeout period,  $t_{TXD\_DTO}$ . The DTO circuit timer starts on a falling edge on the TXD pin. The DTO circuit disables the CAN bus driver if no rising edge occurs before the timeout period expires, which frees the bus for communication between other nodes on the network. The CAN driver is activated again when a recessive signal occurs on the TXD pin, clearing the TXD

DTO condition. The receiver and RXD pin still reflect activity on the CAN bus, and the bus terminals are biased to the recessive level during a TXD dominant timeout.

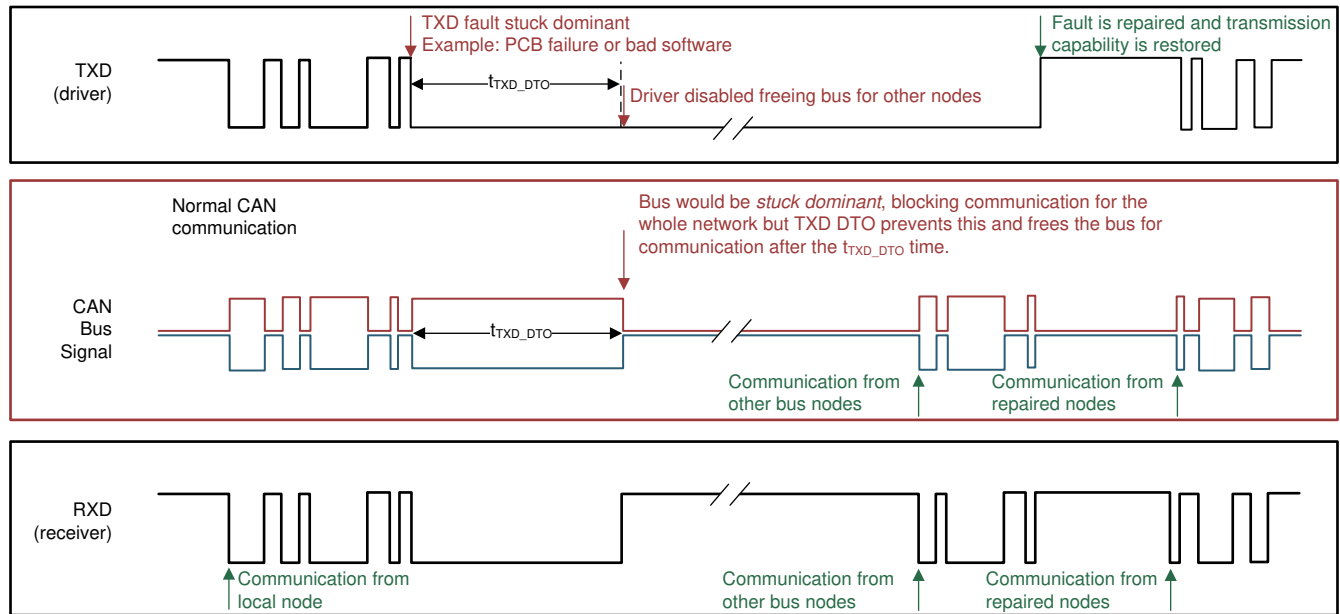


图 8-3. Example Timing Diagram for TXD DTO

#### 备注

The minimum dominant TXD time ( $t_{TXD\_DTO}$ ) allowed by the TXD DTO circuit limits the minimum possible transmitted data rate of the device. The CAN protocol allows a maximum of eleven successive dominant bits (on TXD) for the worst case, where five successive dominant bits are followed immediately by an error frame. This, along with the  $t_{TXD\_DTO}$  minimum, limits the minimum data rate. Calculate the minimum transmitted data rate with [方程式 1](#).

$$\text{Minimum Data Rate} = 11 / t_{TXD\_DTO} \quad (1)$$

#### 8.3.3.2 Thermal Shutdown (TSD)

If the junction temperature of the device exceeds the thermal shutdown threshold ( $T_{TSD}$ ), the device turns off the CAN driver circuits, blocking the TXD-to-bus transmission path. The CAN bus terminals are biased to the recessive level during a thermal shutdown, and the receiver-to-RXD path remains operational. The shutdown condition is cleared when the junction temperature drops at least the thermal shutdown hysteresis temperature ( $T_{TSD\_HYST}$ ) below the thermal shutdown temperature ( $T_{TSD}$ ) of the device.

#### 8.3.3.3 Undervoltage Lockout and Default State

The supply pins have undervoltage detection that places the device in protected or default mode which protects the bus during an undervoltage event on the  $V_{CC1}$  or  $V_{CC2}$  supply pins. If the bus-side power supply,  $V_{CC2}$ , is less than about 4 V, the power shutdown circuits in the ISO1042-Q1 device disable the transceiver to prevent false transmissions because of an unstable supply. If the  $V_{CC1}$  supply is still active when this occurs, the receiver output (RXD) goes to a default HIGH (recessive) value. [表 8-1](#) summarizes the undervoltage lockout and fail-safe behavior.

表 8-1. Undervoltage Lockout and Default State

| $V_{CC1}$     | $V_{CC2}$     | DEVICE STATE | BUS OUTPUT               | RXD          |
|---------------|---------------|--------------|--------------------------|--------------|
| $> UV_{VCC1}$ | $> UV_{VCC2}$ | Functional   | Per Device State and TXD | Mirrors Bus  |
| $< UV_{VCC1}$ | $> UV_{VCC2}$ | Protected    | Recessive                | Undetermined |

**表 8-1. Undervoltage Lockout and Default State (continued)**

| V <sub>CC1</sub>    | V <sub>CC2</sub>     | DEVICE STATE | BUS OUTPUT     | RXD                      |
|---------------------|----------------------|--------------|----------------|--------------------------|
| >UV <sub>VCC1</sub> | < UV <sub>VCC2</sub> | Protected    | High Impedance | Recessive (Default High) |

**备注**

After an undervoltage condition is cleared and the supplies have returned to valid levels, the device typically resumes normal operation in 300 μs.

### 8.3.3.4 Floating Pins

Pullup and pulldown resistors should be used on critical pins to place the device into known states if the pins float. The TXD pin should be pulled up through a resistor to the V<sub>CC1</sub> pin to force a recessive input level if the microprocessor output to the pin floats.

### 8.3.3.5 Unpowered Device

The device is designed to be *ideal passive* or *no load* to the CAN bus if it is unpowered. The bus pins (CANH, CANL) have extremely low leakage currents when the device is unpowered to avoid loading down the bus which is critical if some nodes of the network are unpowered while the rest of the of network remains in operation.

### 8.3.3.6 CAN Bus Short Circuit Current Limiting

The device has two protection features that limit the short circuit current when a CAN bus line has a short-circuit fault condition. The first protection feature is driver current limiting (both dominant and recessive states) and the second feature is TXD dominant state time out to prevent permanent higher short circuit current of the dominant state during a system fault. During CAN communication the bus switches between dominant and recessive states, therefore the short circuit current may be viewed either as the instantaneous current during each bus state or as an average current of the two states. For system current (power supply) and power considerations in the termination resistors and common-mode choke ratings, use the average short circuit current. Determine the ratio of dominant and recessive bits by the data in the CAN frame plus the following factors of the protocol and PHY that force either recessive or dominant at certain times:

- Control fields with set bits
- Bit stuffing
- Interframe space
- TXD dominant time out (fault case limiting)

These factors ensure a minimum recessive amount of time on the bus even if the data field contains a high percentage of dominant bits. The short circuit current of the bus depends on the ratio of recessive to dominant bits and their respective short circuit currents. Use [方程式 2](#) to calculate the average short circuit current.

$$I_{OS(AVG)} = \%Transmit \times [(\%REC\_Bits \times I_{OS(SS)\_REC}) + (\%DOM\_Bits \times I_{OS(SS)\_DOM})] + [\%Receive \times I_{OS(SS)\_REC}] \quad (2)$$

where

- $I_{OS(AVG)}$  is the average short circuit current
- %Transmit is the percentage the node is transmitting CAN messages
- %Receive is the percentage the node is receiving CAN messages
- %REC\_Bits is the percentage of recessive bits in the transmitted CAN messages
- %DOM\_Bits is the percentage of dominant bits in the transmitted CAN messages
- $I_{OS(SS)\_REC}$  is the recessive steady state short circuit current
- $I_{OS(SS)\_DOM}$  is the dominant steady state short circuit current

## 备注

Consider the short circuit current and possible fault cases of the network when sizing the power ratings of the termination resistance and other network components.

## 8.4 Device Functional Modes

表 8-2 和 表 8-3 list the driver and receiver functions. 表 8-4 lists the functional modes for the ISO1042-Q1 device.

表 8-2. Driver Function Table

| INPUT              | OUTPUTS             |                     | DRIVEN BUS STATE |
|--------------------|---------------------|---------------------|------------------|
| TXD <sup>(1)</sup> | CANH <sup>(1)</sup> | CANL <sup>(1)</sup> |                  |
| L                  | H                   | L                   | Dominant         |
| H                  | Z                   | Z                   | Recessive        |

(1) H = high level, L = low level, Z = common mode (recessive) bias to  $V_{CC} / 2$ . See 图 8-1 and 图 8-2 for bus state and common mode bias information.

表 8-3. Receiver Function Table

| DEVICE MODE | CAN DIFFERENTIAL INPUTS<br>$V_{ID} = V_{CANH} - V_{CANL}$ <sup>(3)</sup> | BUS STATE | RXD PIN <sup>(1)</sup> |
|-------------|--------------------------------------------------------------------------|-----------|------------------------|
| Normal      | $V_{ID} \geq V_{IT(MAX)}$                                                | Dominant  | L                      |
|             | $V_{IT(MIN)} < V_{ID} < V_{IT(MAX)}$                                     | ?         | ?                      |
|             | $V_{ID} \leq V_{IT(MIN)}$                                                | Recessive | H                      |
|             | Open ( $V_{ID} \approx 0$ V)                                             | Open      | H                      |

(1) H = high level, L = low level, ? = indeterminate.

表 8-4. Function Table

| DRIVER                |         |      |           | RECEIVER                                                     |               |           |
|-----------------------|---------|------|-----------|--------------------------------------------------------------|---------------|-----------|
| INPUTS <sup>(1)</sup> | OUTPUTS |      | BUS STATE | DIFFERENTIAL INPUTS<br>$V_{ID} = CANH - CANL$ <sup>(3)</sup> | OUTPUT<br>RXD | BUS STATE |
| TXD                   | CANH    | CANL |           |                                                              |               |           |
| L <sup>(2)</sup>      | H       | L    | DOMINANT  | $V_{ID} \geq V_{IT(MAX)}$                                    | L             | DOMINANT  |
| H                     | Z       | Z    | RECESSIVE | $V_{IT(MIN)} < V_{ID} < V_{IT(MAX)}$                         | ?             | ?         |
| Open                  | Z       | Z    | RECESSIVE | $V_{ID} \leq V_{IT(MIN)}$                                    | H             | RECESSIVE |
| X                     | Z       | Z    | RECESSIVE | Open ( $V_{ID} \approx 0$ V)                                 | H             | RECESSIVE |

(1) H = high level; L = low level; X = irrelevant; ? = indeterminate; Z = high impedance

(2) Logic low pulses to prevent dominant time-out.

(3) See Receiver Electrical Characteristics section for input thresholds.

## 9 Application and Implementation

### 备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The ISO1042-Q1 device can be used with other components from Texas Instruments such as a microcontroller, a transformer driver, and a linear voltage regulator to form a fully isolated CAN interface.

### 9.2 Typical Application

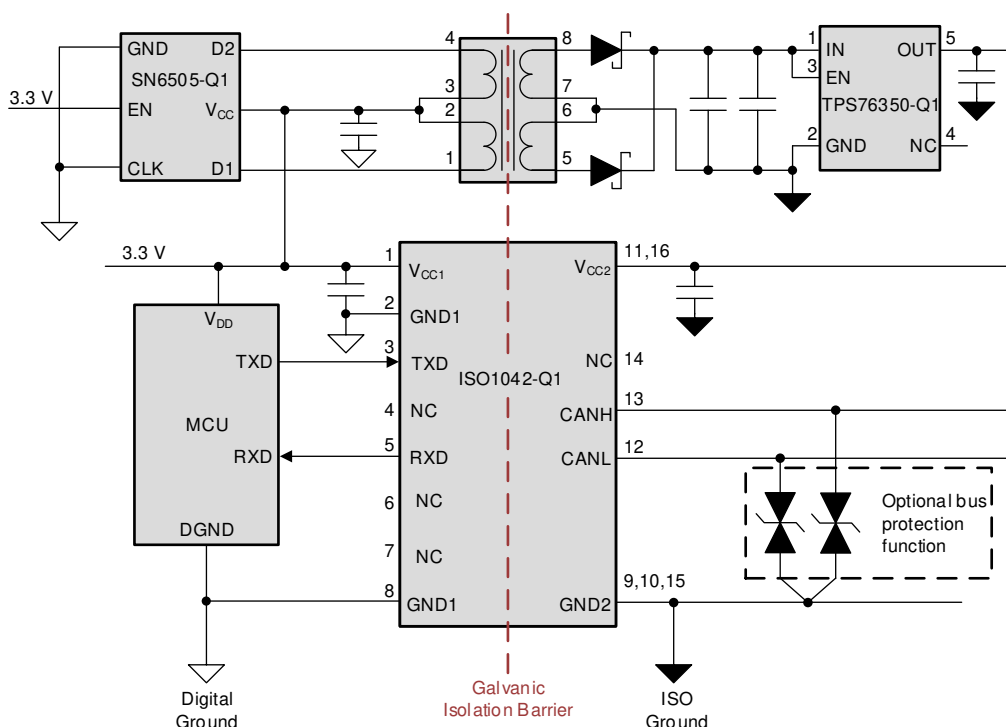


图 9-1. Application Circuit With ISO1042-Q1 in 16-SOIC Package

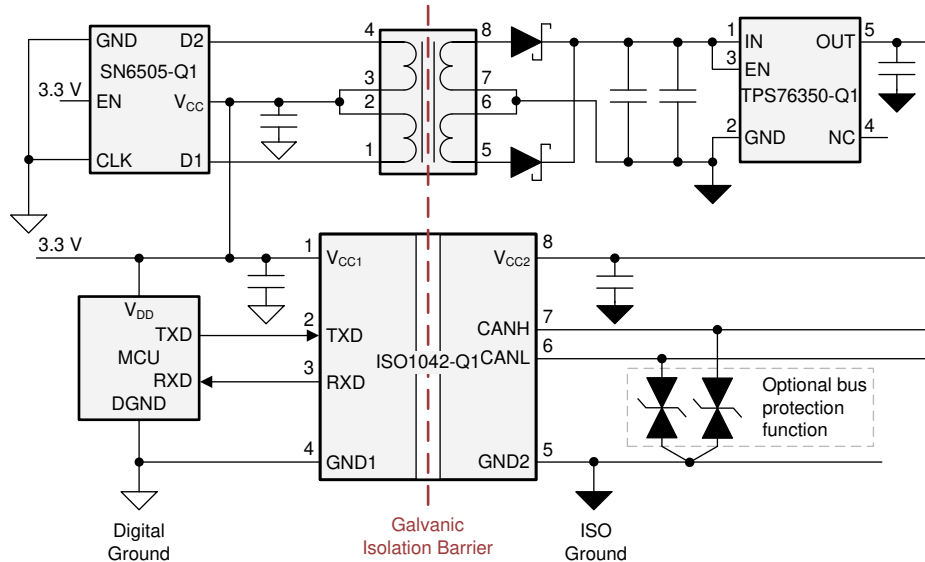


图 9-2. Application Circuit With ISO1042-Q1 in 8-SOIC Package

### 9.2.1 Design Requirements

Unlike an optocoupler-based solution, which requires several external components to improve performance, provide bias, or limit current, the ISO1042-Q1 device only requires external bypass capacitors to operate.

### 9.2.2 Detailed Design Procedure

#### 9.2.2.1 Bus Loading, Length and Number of Nodes

The ISO 11898-2 Standard specifies a maximum bus length of 40 m and maximum stub length of 0.3 m. However, with careful design, users can have longer cables, longer stub lengths, and many more nodes to a bus. A large number of nodes requires transceivers with high input impedance such as the ISO1042-Q1 transceivers.

Many CAN organizations and standards have scaled the use of CAN for applications outside the original ISO 11898-2 Standard. These organizations and standards have made system-level trade-offs for data rate, cable length, and parasitic loading of the bus. Examples of some of these specifications are ARINC825, CANopen, DeviceNet, and NMEA2000.

The ISO1042-Q1 device is specified to meet the 1.5-V requirement with a 50-Ω load, incorporating the worst case including parallel transceivers. The differential input resistance of the ISO1042-Q1 device is a minimum of 30 kΩ. If 100 ISO1042-Q1 transceivers are in parallel on a bus, this requirement is equivalent to a 300-Ω differential load worst case. That transceiver load of 300 Ω in parallel with the 60 Ω gives an equivalent loading of 50 Ω. Therefore, the ISO1042-Q1 device theoretically supports up to 100 transceivers on a single bus segment. However, for CAN network design margin must be given for signal loss across the system and cabling, parasitic loadings, network imbalances, ground offsets and signal integrity, therefore a practical maximum number of nodes is typically much lower. Bus length may also be extended beyond the original ISO 11898 standard of 40 m by careful system design and data-rate tradeoffs. For example, CANopen network design guidelines allow the network to be up to 1 km with changes in the termination resistance, cabling, less than 64 nodes, and a significantly lowered data rate.

This flexibility in CAN network design is one of the key strengths of the various extensions and additional standards that have been built on the original ISO 11898-2 CAN standard. Using this flexibility requires the responsibility of good network design and balancing these tradeoffs.

#### 9.2.2.2 CAN Termination

The ISO11898 standard specifies the interconnect to be a single twisted pair cable (shielded or unshielded) with 120-Ω characteristic impedance ( $Z_0$ ). Resistors equal to the characteristic impedance of the line should be used

to terminate both ends of the cable to prevent signal reflections. Unterminated drop-lines (stubs) connecting nodes to the bus should be kept as short as possible to minimize signal reflections. The termination may be in a node, but if nodes are removed from the bus, the termination must be carefully placed so that it is not removed from the bus.

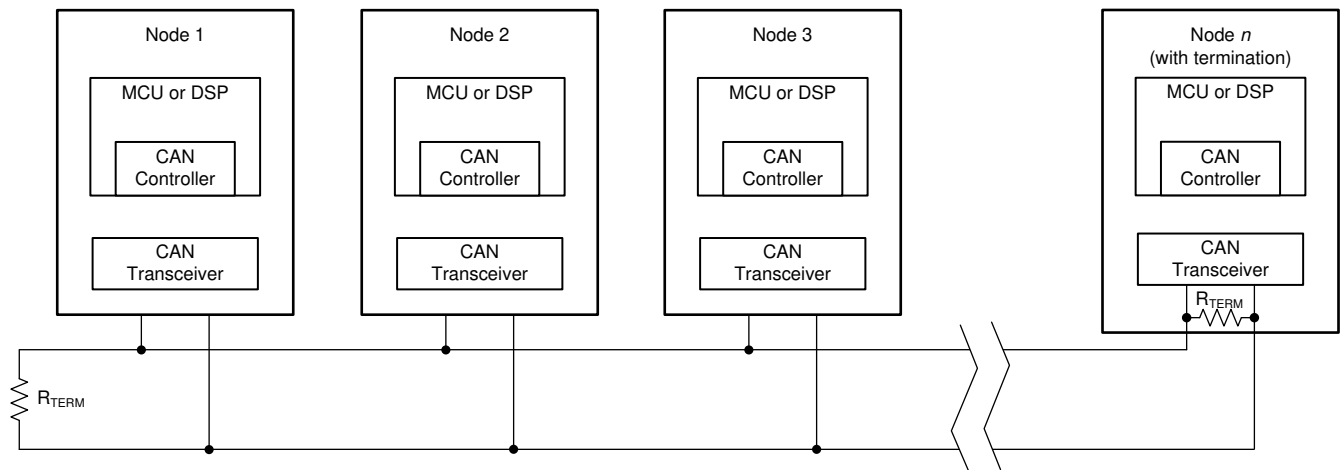


图 9-3. Typical CAN Bus

Termination may be a single 120- $\Omega$  resistor at the end of the bus, either on the cable or in a terminating node. If filtering and stabilization of the common-mode voltage of the bus is desired, then split termination can be used. (See 图 9-4). Split termination improves the electromagnetic emissions behavior of the network by eliminating fluctuations in the bus common-mode voltages at the start and end of message transmissions.

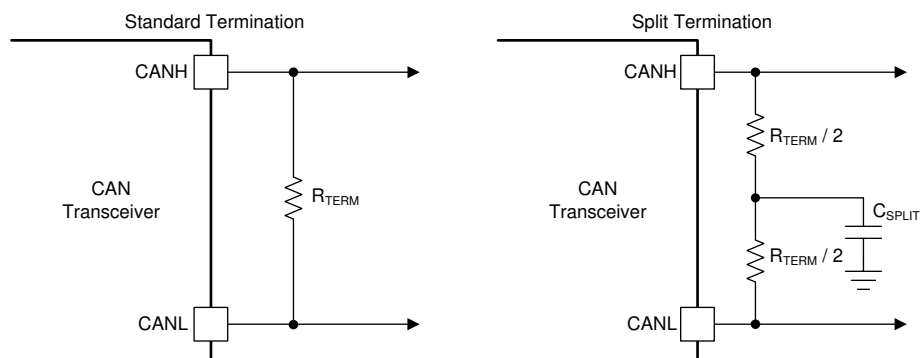


图 9-4. CAN Bus Termination Concepts

### 9.2.3 Application Curve

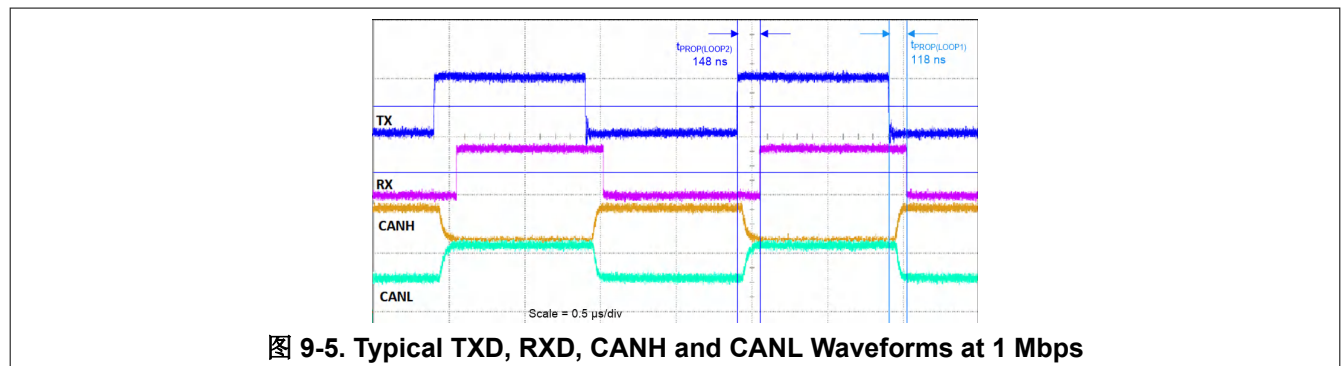


图 9-5. Typical TXD, RXD, CANH and CANL Waveforms at 1 Mbps

## 10 Power Supply Recommendations

To make sure operation is reliable at all data rates and supply voltages, a 0.1- $\mu$ F bypass capacitor is recommended at the input and output supply pins ( $V_{CC1}$  and  $V_{CC2}$ ). The capacitors should be placed as close to the supply pins as possible. In addition, a bulk capacitance, typically 4.7  $\mu$ F, should be placed near the  $V_{CC2}$  supply pin. If only a single primary-side power supply is available in an application, isolated power can be generated for the secondary-side with the help of a transformer driver such as TI's [SN6505B](#). For such applications, detailed power supply design, and transformer selection recommendations are available in the [SN6505 Low-Noise 1-A Transformer Drivers for Isolated Power Supplies data sheet](#).

## 11 Layout

### 11.1 Layout Guidelines

A minimum of four layers is required to accomplish a low EMI PCB design (see 节 11.2). Layer stacking should be in the following order (top-to-bottom): high-speed signal layer, ground plane, power plane and low-frequency signal layer.

- Routing the high-speed traces on the top layer avoids the use of vias (and the introduction of their inductances) and allows for clean interconnects between the isolator and the transmitter and receiver circuits of the data link.
- Placing a solid ground plane next to the high-speed signal layer establishes controlled impedance for transmission line interconnects and provides an excellent low-inductance path for the return current flow.
- Placing the power plane next to the ground plane creates additional high-frequency bypass capacitance of approximately 100 pF/in<sup>2</sup>.
- Routing the slower speed control signals on the bottom layer allows for greater flexibility as these signal links usually have margin to tolerate discontinuities such as vias.

Suggested placement and routing of ISO1042-Q1 bypass capacitors and optional TVS diodes is shown in 图 11-2 and 图 11-3. In particular, place the  $V_{CC2}$  bypass capacitors on the top layer, as close to the device pins as possible, and complete the connection to the  $V_{CC2}$  and  $G_{ND2}$  pins without using vias. Note that the SOIC-16 variant needs two  $V_{CC2}$  bypass capacitor, one on each  $V_{CC2}$  pin.

If an additional supply voltage plane or signal layer is needed, add a second power or ground plane system to the stack to keep it symmetrical. This makes the stack mechanically stable and prevents it from warping. Also the power and ground plane of each power system can be placed closer together, thus increasing the high-frequency bypass capacitance significantly.

For detailed layout recommendations, refer to the [Digital Isolator Design Guide](#).

#### 11.1.1 PCB Material

For digital circuit boards operating at less than 150 Mbps, (or rise and fall times greater than 1 ns), and trace lengths of up to 10 inches, use standard FR-4 UL94V-0 printed circuit board. This PCB is preferred over lower-cost alternatives because of lower dielectric losses at high frequencies, less moisture absorption, greater strength and stiffness, and the self-extinguishing flammability-characteristics.

### 11.2 Layout Example

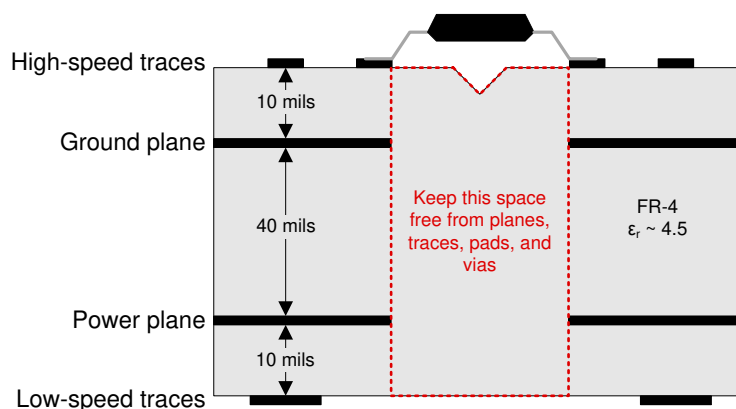


图 11-1. Recommended Layer Stack

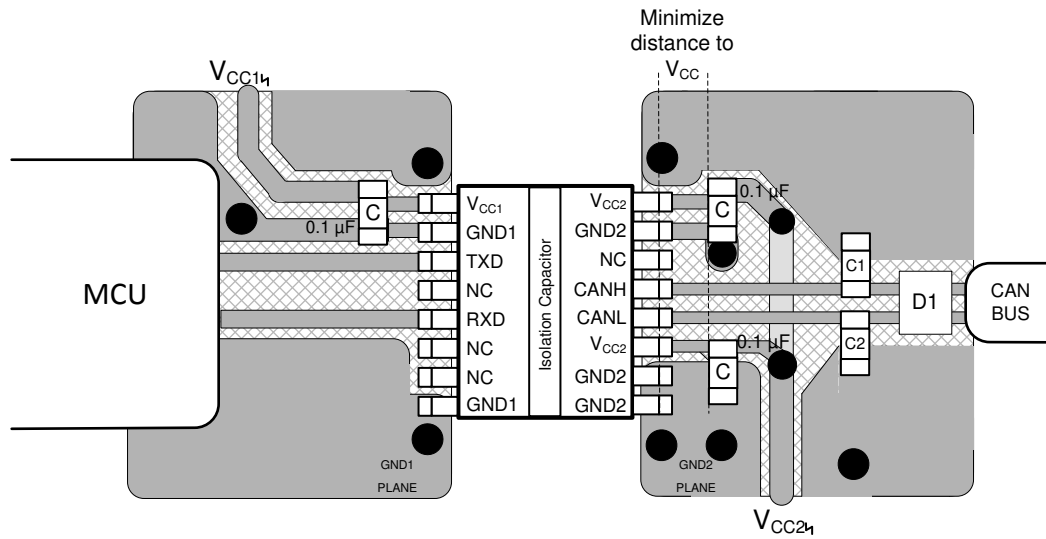


图 11-2. 16-DW Layout Example

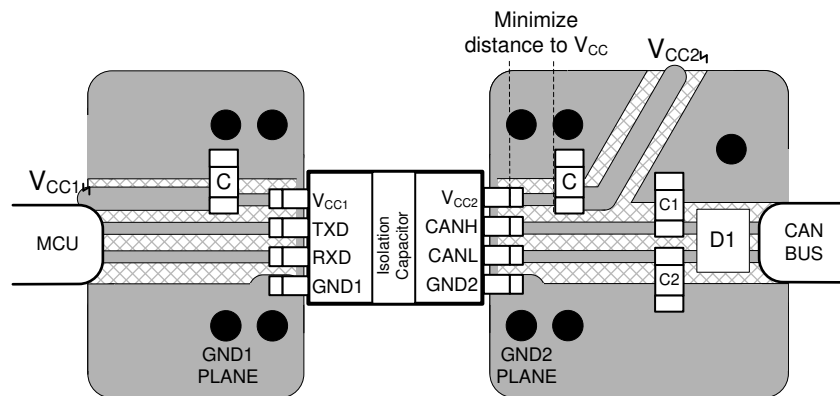


图 11-3. 8-DWV Layout Example

## 12 Device and Documentation Support

### 12.1 Documentation Support

#### 12.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, [Digital Isolator Design Guide](#)
- Texas Instruments, [ISO1042DW Isolated CAN Transceiver Evaluation Module User's Guide](#)
- Texas Instruments, [Isolate your CAN systems without compromising on performance or space TI TechNote](#)
- Texas Instruments, [Isolation Glossary](#)
- Texas Instruments, [High-voltage reinforced isolation: Definitions and test methodologies](#)
- Texas Instruments, [How to Isolate Signal and Power in Isolated CAN Systems TI TechNote](#)
- Texas Instruments, [How to Design Isolated CAN Systems With Correct Bus Protection Application Report](#)

### 12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 12.3 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

### 12.4 Trademarks

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### 12.5 静电放电警告



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ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

### 12.6 术语表

TI 术语表 本术语表列出并解释了术语、首字母缩略词和定义。

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

| Orderable part number           | Status<br>(1) | Material type<br>(2) | Package   Pins | Package qty   Carrier | RoHS<br>(3) | Lead finish/<br>Ball material<br>(4) | MSL rating/<br>Peak reflow<br>(5) | Op temp (°C) | Part marking<br>(6) |
|---------------------------------|---------------|----------------------|----------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|---------------------|
| <a href="#">ISO1042BQDWQ1</a>   | Active        | Production           | SOIC (DW)   16 | 40   TUBE             | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042BQ1          |
| ISO1042BQDWQ1.A                 | Active        | Production           | SOIC (DW)   16 | 40   TUBE             | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042BQ1          |
| <a href="#">ISO1042BQDWRQ1</a>  | Active        | Production           | SOIC (DW)   16 | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042BQ1          |
| ISO1042BQDWRQ1.A                | Active        | Production           | SOIC (DW)   16 | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042BQ1          |
| <a href="#">ISO1042BQDWVQ1</a>  | Active        | Production           | SOIC (DWV)   8 | 64   TUBE             | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042B<br>Q1      |
| ISO1042BQDWVQ1.A                | Active        | Production           | SOIC (DWV)   8 | 64   TUBE             | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042B<br>Q1      |
| <a href="#">ISO1042BQDWVRQ1</a> | Active        | Production           | SOIC (DWV)   8 | 1000   LARGE T&R      | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042B<br>Q1      |
| ISO1042BQDWVRQ1.A               | Active        | Production           | SOIC (DWV)   8 | 1000   LARGE T&R      | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042B<br>Q1      |
| <a href="#">ISO1042QDWQ1</a>    | Active        | Production           | SOIC (DW)   16 | 40   TUBE             | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042Q1           |
| ISO1042QDWQ1.A                  | Active        | Production           | SOIC (DW)   16 | 40   TUBE             | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042Q1           |
| <a href="#">ISO1042QDWRQ1</a>   | Active        | Production           | SOIC (DW)   16 | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042Q1           |
| ISO1042QDWRQ1.A                 | Active        | Production           | SOIC (DW)   16 | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042Q1           |
| <a href="#">ISO1042QDWVQ1</a>   | Active        | Production           | SOIC (DWV)   8 | 64   TUBE             | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042<br>Q1       |
| ISO1042QDWVQ1.A                 | Active        | Production           | SOIC (DWV)   8 | 64   TUBE             | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042<br>Q1       |
| <a href="#">ISO1042QDWVRQ1</a>  | Active        | Production           | SOIC (DWV)   8 | 1000   LARGE T&R      | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042<br>Q1       |
| ISO1042QDWVRQ1.A                | Active        | Production           | SOIC (DWV)   8 | 1000   LARGE T&R      | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 125   | ISO1042<br>Q1       |

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

**(4) Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**(5) MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

**(6) Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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**OTHER QUALIFIED VERSIONS OF ISO1042-Q1 :**

- Catalog : [ISO1042](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

## TAPE AND REEL INFORMATION



\*All dimensions are nominal

| Device          | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| ISO1042BQDWRQ1  | SOIC         | DW              | 16   | 2000 | 330.0              | 16.4               | 10.75   | 10.7    | 2.7     | 12.0    | 16.0   | Q1            |
| ISO1042BQDWVRQ1 | SOIC         | DWV             | 8    | 1000 | 330.0              | 16.4               | 12.05   | 6.15    | 3.3     | 16.0    | 16.0   | Q1            |
| ISO1042QDWRQ1   | SOIC         | DW              | 16   | 2000 | 330.0              | 16.4               | 10.75   | 10.7    | 2.7     | 12.0    | 16.0   | Q1            |
| ISO1042QDWVRQ1  | SOIC         | DWV             | 8    | 1000 | 330.0              | 16.4               | 12.05   | 6.15    | 3.3     | 16.0    | 16.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device          | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| ISO1042BQDWRQ1  | SOIC         | DW              | 16   | 2000 | 350.0       | 350.0      | 43.0        |
| ISO1042BQDWVRQ1 | SOIC         | DWV             | 8    | 1000 | 350.0       | 350.0      | 43.0        |
| ISO1042QDWRQ1   | SOIC         | DW              | 16   | 2000 | 350.0       | 350.0      | 43.0        |
| ISO1042QDWVRQ1  | SOIC         | DWV             | 8    | 1000 | 350.0       | 350.0      | 43.0        |

**TUBE**

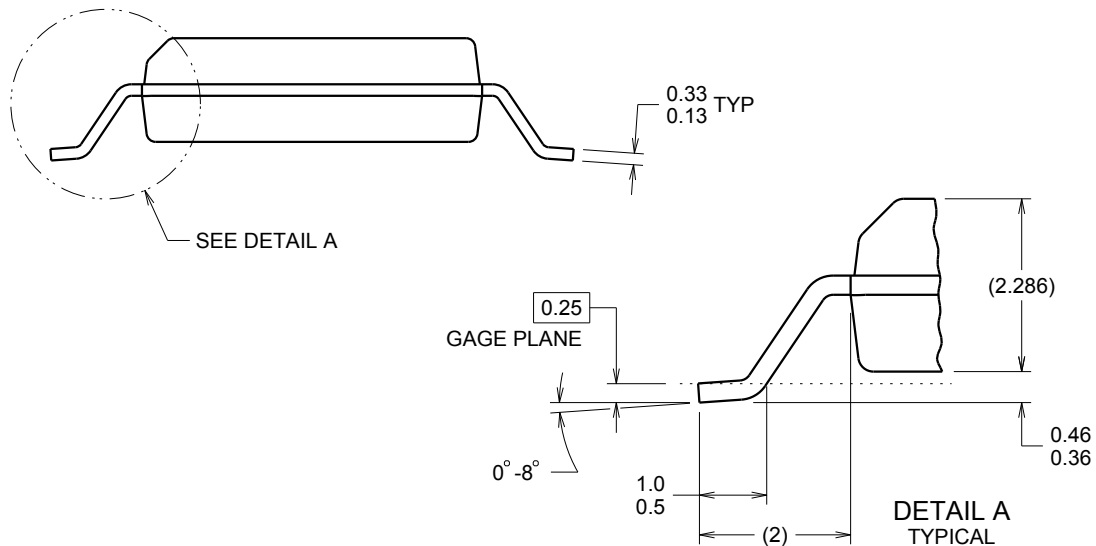

\*All dimensions are nominal

| Device           | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|------------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| ISO1042BQDWQ1    | DW           | SOIC         | 16   | 40  | 506.98 | 12.7   | 4826   | 6.6    |
| ISO1042BQDWQ1.A  | DW           | SOIC         | 16   | 40  | 506.98 | 12.7   | 4826   | 6.6    |
| ISO1042BQDWVQ1   | DWV          | SOIC         | 8    | 64  | 505.46 | 13.94  | 4826   | 6.6    |
| ISO1042BQDWVQ1.A | DWV          | SOIC         | 8    | 64  | 505.46 | 13.94  | 4826   | 6.6    |
| ISO1042QDWQ1     | DW           | SOIC         | 16   | 40  | 506.98 | 12.7   | 4826   | 6.6    |
| ISO1042QDWQ1.A   | DW           | SOIC         | 16   | 40  | 506.98 | 12.7   | 4826   | 6.6    |
| ISO1042QDWVQ1    | DWV          | SOIC         | 8    | 64  | 505.46 | 13.94  | 4826   | 6.6    |
| ISO1042QDWVQ1.A  | DWV          | SOIC         | 8    | 64  | 505.46 | 13.94  | 4826   | 6.6    |

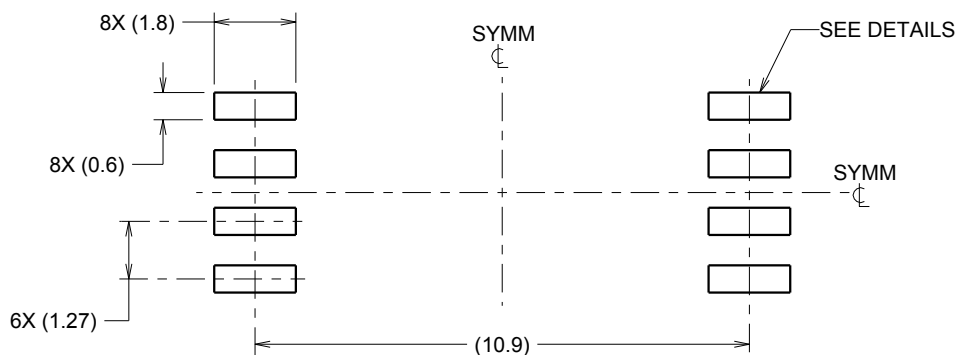


SOIC - 2.8 mm max height

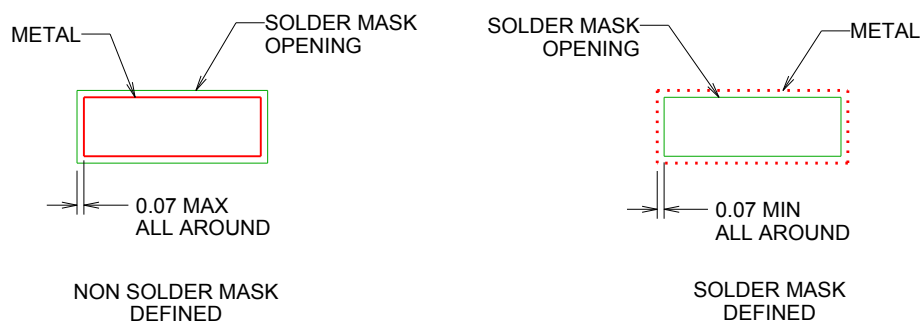
PIN 1 ID AREA  
 11.5 ± 0.25 TYP  
 5.95  
 5.75  
 NOTE 3  
 1  
 4  
 8  
 5  
 6X 1.27  
 2X 3.81  
 8X 0.51  
 0.31  
 7.6  
 7.4  
 NOTE 4  
 A  
 B  
 SEATING PLANE  
 0.1 C  
 2.8 MAX  
 C  
 A  
 B



1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



**LAND PATTERN EXAMPLE**  
9.1 mm NOMINAL CLEARANCE/CREEPAGE  
SCALE:6X

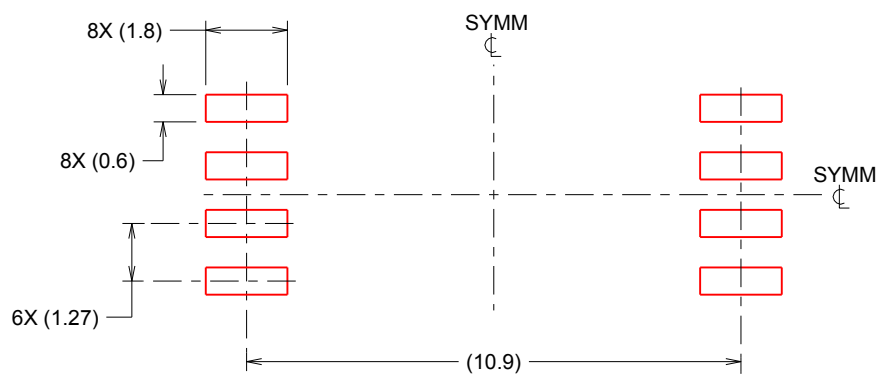


**SOLDER MASK DETAILS**

4218796/A 09/2013

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE  
 BASED ON 0.125 mm THICK STENCIL  
 SCALE:6X

4218796/A 09/2013

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

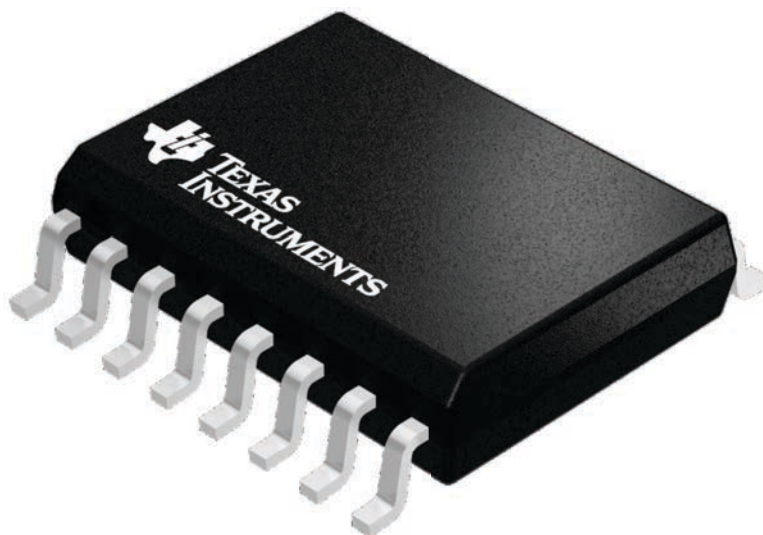
**DW 16**

**SOIC - 2.65 mm max height**

7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4224780/A



DW0016B

# PACKAGE OUTLINE

## SOIC - 2.65 mm max height

SOIC



4221009/B 07/2016

### NOTES:

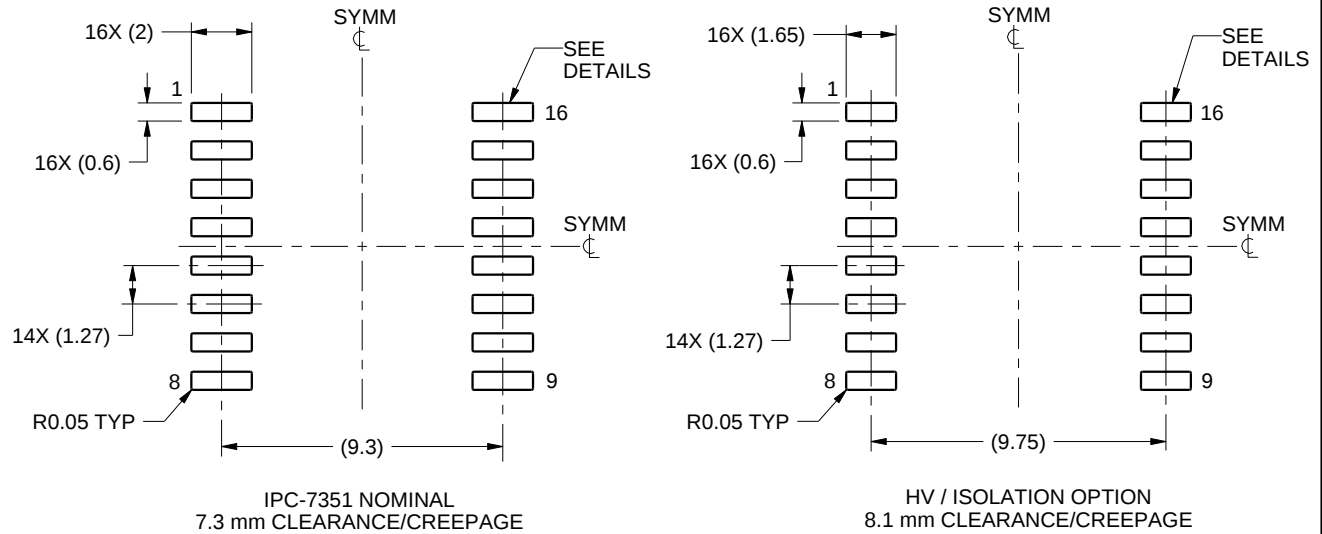
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

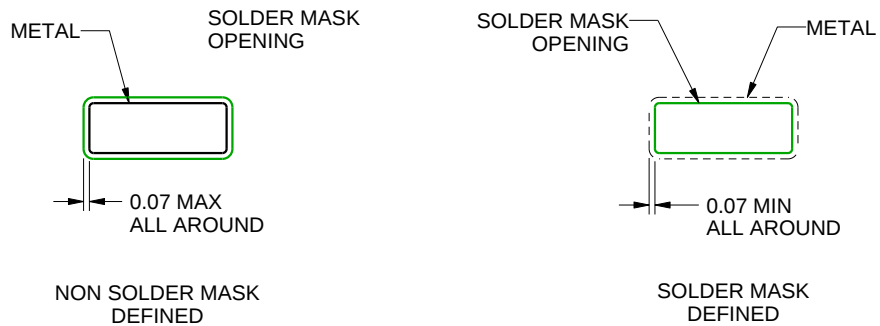
DW0016B

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:4X



SOLDER MASK DETAILS

4221009/B 07/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

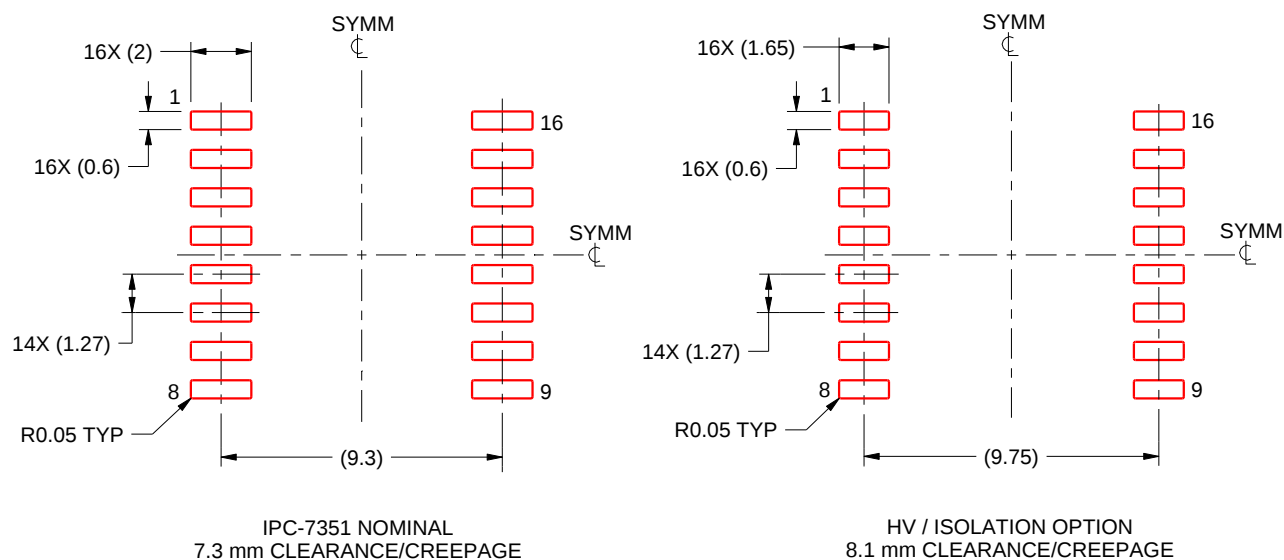
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0016B

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:4X

4221009/B 07/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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最后更新日期：2025 年 10 月